

Qualification requirements are removed for device types 02, 03 and 09 (see 1.1)

MIL-M-38510/10C  
3 March 1986  
SUPERSEDING  
MIL-M-38510/10B  
2 January 1976

MILITARY SPECIFICATION

MICROCIRCUITS, DIGITAL, BIPOLAR, TTL, DECODERS,  
MONOLITHIC SILICON

This specification is approved for use by all Departments and Agencies of the Department of Defense.

1. SCOPE.

1.1 Scope. This specification covers the detail requirements for monolithic silicon, TTL, microcircuit decoders. Qualification inspection requirements are removed for device types 02, 03, and 09. These device types are inactive for new design after the date of this revision. For the remaining device types 01, 04, 05, 06, 07, and 08, two product assurance classes and a choice of case outlines and lead finishes are provided and are reflected in the complete part number.

1.2 Part number. The part number shall be in accordance with MIL-M-38510, with the exception that the "JAN" or "J" certification mark shall not be used for devices 02, 03, and 09.

1.2.1 Device type. The device type shall be as shown in the following:

Device type	Circuit
01	BCD-to-decimal decoder
02 1/	Excess-3-to-decimal decoder
03 1/	Excess-3-gray-to-decimal decoder
04	BCD-to-decimal decoder/driver (30-volt, open collector output)
05	BCD-to-decimal decoder/driver (15-volt, open collector output)
06	BCD-to-seven-segment decoder/driver (30-volt, open collector output)
07	BCD-to-seven-segment decoder/driver (15-volt, open collector output)
08	BCD-to-seven-segment decoder/driver
09 1/	BCD-to-seven-segment decoder/driver (5.5-volt, open collector output)

1.2.2 Device class. The device class shall be the product assurance level as defined in MIL-M-38510.

1.2.3 Case outline. The case outline shall be designated as follows:

Letter	Case outline (see MIL-M-38510, appendix C)
A	F-1 (14-pin, 1/4" x 1/4"), flat-package
B	F-3 (14-pin, 3/16" x 1/4"), flat-package
C	D-1 (14-pin, 1/4" x 3/4"), dual-in-line package
D	F-2 (14-pin, 1/4" x 3/8"), flat-package
E	D-2 (16-pin, 1/4" x 7/8"), dual-in-line package
F	F-5 (16-pin, 1/4" x 3/8"), flat-package

1.2.4 Absolute maximum ratings.

Supply voltage range	-0.5 to 7.0 V dc
Input voltage range	-1.5 V dc at -12 mA to 5.5 V dc
Storage temperature range	-65°C to 150°C

1/ Qualification requirements are removed for these device types.

Beneficial comments (recommendations, additions, deletions) and any pertinent data which may be of use in improving this document should be addressed to: Rome Air Development Center (RBE-2), Griffiss AFB, NY 13441, by using the self-addressed Standardization Document Improvement Proposal (DD Form 1426) appearing at the end of this document or by letter.

Maximum power dissipation, ( $P_D$ ) <u>2</u> /- - - - -	226 mW dc (device types 01, 02 and 03) <u>3</u> / 341 mW dc (device types 04 and 05) 467 mW dc (device types 06, 07, 08 and 09) <u>3</u> /
Lead temperature (soldering, 10 seconds) - - - - -	300°C
Thermal resistance, junction to case ( $\theta_{JC}$ ): Cases A, B, C, D, E, F - - - - -	(See MIL-M-38510, appendix C)
Junction temperature ( $T_J$ ) <u>4</u> /- - - - -	+175°C
Maximum current into any output (output off): Device types 04, 05, 06, 07 and 09 <u>3</u> / - - - - -	1 mA

### 1.2.5 Recommended operating conditions.

Supply voltage ( $V_{CC}$ ) - - - - -	4.5 V dc minimum to 5.5 V dc maximum
Minimum high level input voltage ( $V_{IH}$ ) - - - - -	2.0 V dc
Maximum low level input voltage ( $V_{IL}$ ) - - - - -	0.8 V dc
Sink-current capability by device type:	
01, 02, 03 <u>3</u> /- - - - -	16 mA
04, 05 - - - - -	20 mA
06, 07 outputs a-g. - - - - -	40 mA
BI/RBO node - - - - -	8 mA
08 outputs a-g. - - - - -	6.4 mA
BI/RBO node - - - - -	8 mA
09 <u>3</u> / - - - - -	10 mA
Case operating temperature range ( $T_C$ ) - - - - -	-55°C to +125°C

## 2. APPLICABLE DOCUMENT

### 2.1 Government documents.

2.1.1 Specification and standard. The following specification and standard form a part of this specification to the extent specified herein. Unless otherwise specified, the issues of these documents shall be those listed in the issue of the Department of Defense Index of Specifications and Standards (DODISS) and supplement thereto, cited in the solicitation.

#### SPECIFICATION

##### MILITARY

MIL-M-38510 - Microcircuits, General Specification for.

#### STANDARD

##### MILITARY

MIL-STD-883 - Test Methods and Procedures for Microcircuits.

(Copies of the specification and standard required by contractors in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

2.2 Order of precedence. In the event of a conflict between the text of this specification and the references cited herein (except for associated detail specifications, specification sheets or MS standards), the text of this specification shall take precedence. Nothing in this specification, however, shall supersede applicable laws and regulations unless a specific exemption has been obtained.

## 3. REQUIREMENTS

3.1 Detail specifications. The individual item requirements shall be in accordance with MIL-M-38510, and as specified herein.

2/ Must withstand the added  $P_D$  due to short circuit condition (i.e.,  $I_{OS}$ ) at one output for 5 seconds duration

3/ Qualification requirement are removed for devices 02, 03, and 09.

4/ Maximum junction temperature shall not be exceeded except for allowable short duration burn-in screening per method 5004 of MIL-STD-883.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.

3.2.1 Logic diagram and terminal connections. The logic diagram and terminal connections shall be as specified on figures 1 and 2.

3.2.2 Truth tables. The truth tables shall be as specified on figure 3.

3.2.3 Case outlines. Case outlines shall be in accordance with 1.2.3.

3.2.4 Schematic circuits. Schematic circuits shall be submitted to the preparing activity prior to inclusion of a manufacturer's device in the specification and shall be submitted to the qualifying activity and agent activity (DESC-ECS) as a prerequisite for qualification. All qualified manufacturers schematics shall be maintained by the agent activity and will be available upon request.

3.3 Lead material and finish. The lead material and finish shall be in accordance with MIL-M-38510 (see 6.4).

3.4 Electrical performance characteristics. Unless otherwise specified, the electrical performance characteristics are as specified in table I, and apply over the full recommended case operating temperature range.

TABLE I. Electrical performance characteristics, device types 01, 02 and 03 1/

Test	Symbol	Conditions $-55^{\circ}\text{C} \leq T_C \leq +125^{\circ}\text{C}$	Limits		Units
			Min	Max	
High-level output voltage	$V_{OH}$	$V_{CC} = 4.5 \text{ V}, I_{OH} = -0.8 \text{ mA}$	2.4	---	V
Low-level output voltage	$V_{OL}$	$V_{CC} = 4.5 \text{ V}, I_{OL} = 16 \text{ mA}$ $V_{IN} = 0.8 \text{ V and } 2.0 \text{ V}$	---	0.4	V
Input clamp voltage	$V_{IC}$	$V_{CC} = 4.5 \text{ V}, I_{IN} = -12 \text{ mA}$	---	-1.5	V
Low-level input current	$I_{IL}$	$V_{CC} = 5.5 \text{ V}, V_{IN} = 0.4 \text{ V } 2/$	-0.7	-1.6	mA
High-level input current	$I_{IH1}$	$V_{CC} = 5.5 \text{ V}, V_{IN} = 2.4 \text{ V } 3/$	---	40	$\mu\text{A}$
High-level input current	$I_{IH2}$	$V_{CC} = 5.5 \text{ V}, V_{IN} = 5.5 \text{ V } 3/$		100	$\mu\text{A}$
Short-circuit output current	$I_{OS}$	$V_{CC} = 5.5 \text{ V } 4/$	-20	-55	mA
Supply current	$I_{CC}$	$V_{CC} = 5.5 \text{ V}, V_{IN} = 0 \text{ V}$	---	41	mA
Propagation delay time through two logic levels	$t_{pHL}$	$C_L = 50 \text{ pF minimum}$ $R_L = 390 \Omega \pm 5\%$	5	39	ns
Propagation delay time through two logic levels	$t_{pLH}$	(Figure 5)	5	39	ns
Propagation delay time through three logic levels	$t_{pHL}$		5	46	ns
Propagation delay time through three logic levels	$t_{pLH}$		5	45	ns

- 1/ Qualification requirement are removed for device types 02, and 03.  
 2/ All unspecified inputs at 5.5 volts.  
 3/ All unspecified inputs grounded.  
 4/ Not more than one output should be shorted at one time.

TABLE I. Electrical performance characteristics, device types 04 and 05.

Test	Symbol	Conditions $-55^{\circ}\text{C} \leq T_C \leq +125^{\circ}\text{C}$	Limits		Units
			Min	Max	
Low-level output voltage	$V_{OL1}$	$V_{CC} = 4.5 \text{ V}, I_{OL} = 80 \text{ mA}$	---	0.9	V
Low-level output voltage	$V_{OL2}$	$V_{CC} = 4.5 \text{ V}, I_{OL} = 20 \text{ mA}$	---	0.4	V
Input clamp voltage	$V_{IC}$	$V_{CC} = 4.5 \text{ V}, I_{IN} = -12 \text{ mA}$	---	-1.5	V
Maximum collector cut-off current	$I_{CEX}$	$V_{CC} = 4.5 \text{ V}, V_{OH} = \text{max } \underline{1/}$		250	$\mu\text{A}$
Low-level input current	$I_{IL}$	$V_{CC} = 5.5 \text{ V}, V_{IN} = 0.4 \text{ V } \underline{2/}$	-0.7	-1.6	mA
High-level input current	$I_{IH1}$	$V_{CC} = 5.5 \text{ V}, V_{IN} = 2.4 \text{ V } \underline{3/}$	---	40	$\mu\text{A}$
High-level input current	$I_{IH2}$	$V_{CC} = 5.5 \text{ V}, V_{IN} = 5.5 \text{ V } \underline{3/}$		100	$\mu\text{A}$
Supply current	$I_{CC}$	$V_{CC} = 5.5 \text{ V}, V_{IN} = 0 \text{ V}$	---	62	mA
Propagation delay time to a high logic level	$t_{PLH}$	$C_L = 50 \text{ pF}$ minimum $R_L = 390 \Omega \pm 5\%$	5	73	ns
Propagation delay time to a low logic level	$t_{PHL}$	(Figure 6)	5	73	ns

- 1/ Device type 04 maximum  $V_{OH} = 30 \text{ V}$ .  
Device type 05 maximum  $V_{OH} = 15 \text{ V}$ .  
2/ All unspecified inputs at 5.5 volts.  
3/ All unspecified inputs grounded.

TABLE I. Electrical performance characteristics, device types 06 and 07.

Test	Symbol	Conditions $-55^{\circ}\text{C} \leq T_C \leq +125^{\circ}\text{C}$	Limits		Units
			Min	Max	
Low-level output voltage <u>1/</u>	$V_{OL1}$	$V_{CC} = 4.5 \text{ V}, I_{OL} = 40 \text{ mA}$	---	0.4	V
Low-level output voltage <u>2/</u>	$V_{OL2}$	$V_{CC} = 4.5 \text{ V}, I_{OL} = 8 \text{ mA}$	---	0.4	V
Input clamp voltage	$V_{IC}$	$V_{CC} = 4.5 \text{ V}, I_{IN} = -12 \text{ mA}$	---	-1.5	V
High-level output voltage <u>2/</u>	$V_{OH}$	$V_{CC} = 4.5 \text{ V}, I_{OH} = -0.2 \text{ mA}$	2.4	---	V
Maximum collector cut-off current <u>3/</u>	$I_{CEX}$	$V_{CC} = 4.5 \text{ V}, V_{OH} = \text{max } \underline{3/}$	---	250	$\mu\text{A}$
Low-level input current <u>4/</u>	$I_{IL1}$	$V_{CC} = 5.5 \text{ V}, V_{IN} = 0.4 \text{ V } \underline{5/}$	-0.4	-1.6	mA
Low-level input current <u>2/</u>	$I_{IL2}$	$V_{CC} = 5.5 \text{ V}, V_{IN} = 0.4 \text{ V } \underline{5/}$	-1.7	-4.2	mA
High-level input current <u>4/</u>	$I_{IH1}$	$V_{CC} = 5.5 \text{ V}, V_{IN} = 2.4 \text{ V } \underline{6/}$	---	40	$\mu\text{A}$
High-level input current <u>4/</u>	$I_{IH2}$	$V_{CC} = 5.5 \text{ V}, V_{IN} = 5.5 \text{ V } \underline{6/}$		100	$\mu\text{A}$
Short-circuit output current <u>1/</u>	$I_{OS}$	$V_{CC} = 5.5 \text{ V } \underline{6/}$	---	-4	mA
Supply current	$I_{CC}$	$V_{CC} = 5.5 \text{ V}, V_{IN} = 5.5 \text{ V}$	---	85	mA
Propagation delay time from any input except RBI to any output	$t_{PLH}$	$C_L = 50 \text{ pF}$ minimum $R_L = 120 \Omega \pm 5\% \underline{1/}$ $R_L = 560 \Omega \pm 5\% \underline{2/}$ (Figure 7)	8	144	ns
Propagation delay time from RBI to any output	$t_{PLH}$		8	144	ns
Propagation delay time from any input except RBI to any out	$t_{PHL}$		8	144	ns
Propagation delay time from RBI to any output	$t_{PHL}$		8	144	ns

1/ Outputs a through g only.

2/ BI/RBO node only.

3/ Device type 06 maximum  $V_{OH} = 30 \text{ V}$ .  
Device type 07 maximum  $V_{OH} = 15 \text{ V}$ .

4/ Any input except BI/RBO node.

5/ All unspecified inputs at 5.5 volts.

6/ All unspecified inputs grounded.

TABLE I. Electrical performance characteristics, device type 08.

Test	Symbol	Conditions $-55^{\circ}\text{C} \leq T_C \leq +125^{\circ}\text{C}$	Limits		Units
			Min	Max	
High-level output voltage <u>1/</u>	$V_{OH1}$	$V_{CC} = 4.5 \text{ V}, I_{OH} = -0.4 \text{ mA}$	2.4	---	V
High-level output voltage <u>2/</u>	$V_{OH2}$	$V_{CC} = 4.5 \text{ V}, I_{OH} = -0.2 \text{ mA}$	2.4	---	V
Low-level output voltage <u>1/</u>	$V_{OL1}$	$V_{CC} = 4.5 \text{ V}, I_{OH} = 6.4 \text{ mA}$	---	0.4	V
Low-level output voltage <u>2/</u>	$V_{OL2}$	$V_{CC} = 4.5 \text{ V}, I_{OH} = 8 \text{ mA}$	---	0.4	V
Input clamp voltage	$V_{IC}$	$V_{CC} = 4.5 \text{ V}, I_{IN} = -12 \text{ mA}$	---	-1.5	V
Low-level input current <u>3/</u>	$I_{IL1}$	$V_{CC} = 5.5 \text{ V}, V_{IN} = 0.4 \text{ V}$ <u>4/</u>	-0.4	-1.6	mA
Low-level input current <u>3/</u>	$I_{IL2}$	$V_{CC} = 5.5 \text{ V}, V_{IN} = 0.4 \text{ V}$ <u>4/</u>	-1.7	-4.2	mA
High-level input current <u>3/</u>	$I_{IH1}$	$V_{CC} = 5.5 \text{ V}, V_{IN} = 2.4 \text{ V}$ <u>5/</u>	---	40	$\mu\text{A}$
High-level input current <u>3/</u>	$I_{IH2}$	$V_{CC} = 5.5 \text{ V}, V_{IN} = 5.5 \text{ V}$ <u>5/</u>		100	$\mu\text{A}$
Short-circuit output current	$I_{OS}$	$V_{CC} = 5.5 \text{ V}$	---	-4	mA
Supply current	$I_{CC}$	$V_{CC} = 5.5 \text{ V}, V_{IN} = 0 \text{ V}$	---	76	mA
Propagation delay time from any input except RBI to any output	$t_{PLH}$	$C_L = 50 \text{ pF}$ minimum $R_L = 750\Omega \pm 5\%$ <u>1/</u> $R_L = 560\Omega \pm 5\%$ <u>2/</u> (Figure 8)	8	144	ns
Propagation delay time from RBI to any output	$t_{PLH}$		8	144	ns
Propagation delay time from any input except RBI to any output	$t_{PHL}$		8	144	ns
Propagation delay time from RBI to any output	$t_{PHL}$		8	144	ns

1/ Outputs a through g only.

2/ BI/RBO node only.

3/ Any input except BI/RBO node.

4/ All unspecified inputs at 5.5 volts.

5/ All unspecified inputs grounded.

TABLE I. Electrical performance characteristics, device type 09 1/

Test	Symbol	Conditions $-55^{\circ}\text{C} \leq T_C \leq +125^{\circ}\text{C}$	Limits		Units
			Min	Max	
Low-level output voltage	$V_{OL}$	$V_{CC} = 4.5 \text{ V}, I_{OL} = 10 \text{ mA}$	---	0.4	V
Input clamp voltage	$V_{IC}$	$V_{CC} = 4.5 \text{ V}, I_{IN} = -12 \text{ mA}$	---	-1.5	V
Maximum collector cut-off current	$I_{CEX}$	$V_{CC} = 4.5 \text{ V}, V_{OH} = 5.5 \text{ V}$	---	250	$\mu\text{A}$
Low-level input current	$I_{IL}$	$V_{CC} = 5.5 \text{ V}, V_{IN} = 0.4 \text{ V}$ 2/	-0.4	-1.6	mA
High-level input current	$I_{IH1}$	$V_{CC} = 5.5 \text{ V}, V_{IN} = 2.4 \text{ V}$ 3/	---	40	$\mu\text{A}$
High-level input current	$I_{IH2}$	$V_{CC} = 5.5 \text{ V}, V_{IN} = 5.5 \text{ V}$ 3/	---	100	$\mu\text{A}$
Supply current	$I_{CC}$	$V_{CC} = 5.5 \text{ V}, V_{IN} = 0 \text{ V}$	---	47	mA
Propagation delay time from any input to any output	$t_{PLH}$	$C_L = 50 \text{ pF}$ minimum $R_L = 470\Omega \pm 5\%$ 1/	8	144	ns
Propagation delay time from any input to any output	$t_{PHL}$	(Figure 9)	8	144	ns

1/ Qualification requirements are removed for device type 09.

2/ All unspecified inputs at 5.5 volts.

3/ All unspecified inputs grounded.

3.5 Electrical test requirements. The electrical test requirements for each device class shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table III.

3.6 Marking. Marking shall be in accordance with MIL-M-38510 and 1.2 herein. At the option of the manufacturer, marking of the country of origin may be omitted from the body of the microcircuit, but shall be retained on the initial container. The "JAN" or "J" certification mark shall not be used for device types 02, 03, and 09.

TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (see table III)	
	Class S devices 1/	Class B devices
Interim electrical parameters (method 5004)	1	1
Final electrical test parameters (method 5004)	1*,2,3,7 9,10,11	1*,2,3, 7,9
Group A test requirements (method 5005)	1,2,3,7 8,9,10,11	1,2,3,7,8 9,10,11
Group C and D end-point electrical parameters (method 5005)	1,2,3	1,2,3
Additional electrical subgroups for group C periodic inspections	N/A	N/A

1/ Class S product assurance is not applicable to device types 02, 03, and 09.

\*PDA applies to subgroup 1 (see 4.2c)).

3.7 Microcircuit group assignment. The devices covered by this specification shall be in microcircuit group number 4 (see MIL-M-38510, appendix E).

3.8 Manufacturer eligibility. To be eligible to supply microcircuits to this specification, a manufacturer shall have a manufacturer certification in accordance with MIL-M-38510 for at least one line, not necessarily the line producing the device described herein. This shall apply only for device types 02, 03, and 09.

3.9 Certification. Certification in accordance with MIL-M-38510 is not required for device types 02, 03, and 09, but shall be retained for the remaining device types.

#### 4. QUALITY ASSURANCE PROVISIONS

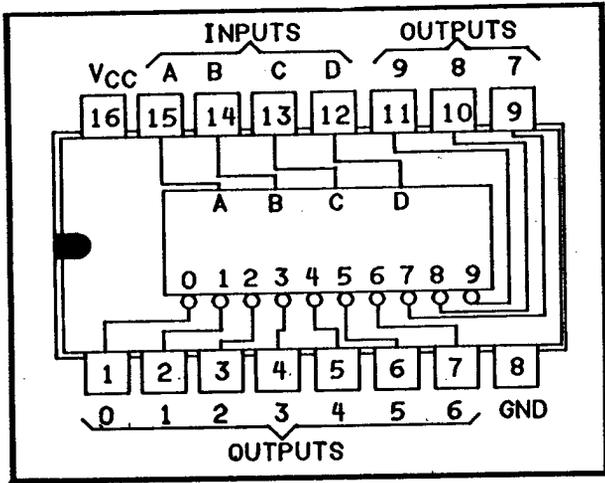
4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with MIL-M-38510 and methods 5005 and 5007, as applicable, of MIL-STD-883, except as modified herein.

4.2 Screening. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on device types 01, 04, 05, 06, 07, and 08 prior to qualification and quality conformance inspection, and on device types 02, 03, and 09 prior to quality conformance inspection. The following additional criteria shall apply:

- a. Burn-in (method 1015 of MIL-STD-883).
  - (1) Test condition D or E, using the circuit shown on figure 4, or equivalent.
  - (2)  $T_A = +125^\circ\text{C}$  minimum.
- b. Interim and final electrical test parameters shall be as specified in table II, except interim electrical parameters test prior to burn-in is optional at the discretion of the manufacturer.
- c. The percent defective allowable (PDA) shall be as specified in MIL-M-38510.

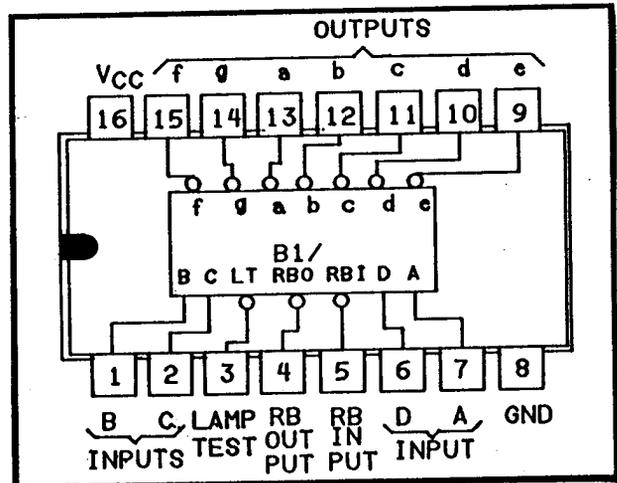
Device types 01, 02, 03, 04, and 05 <sup>1/</sup>

Cases E and F



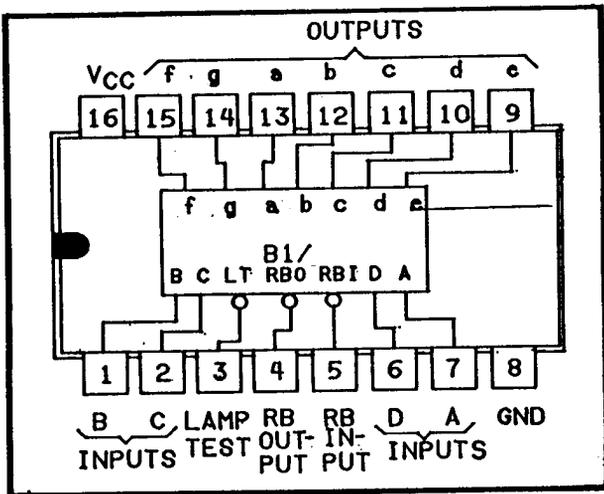
Device types 06 and 07

Cases E and F



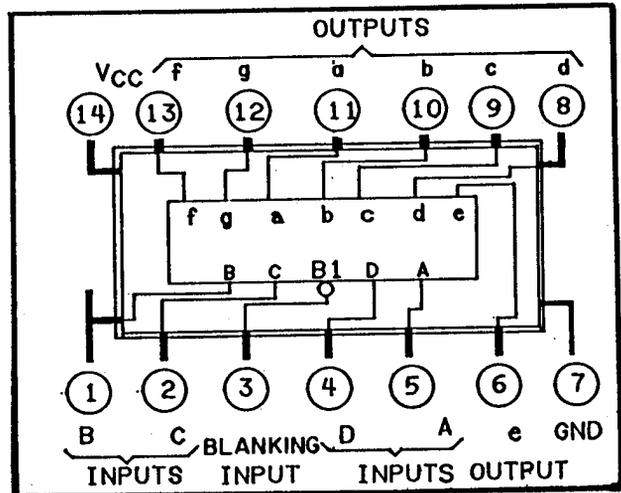
Device type 08

Cases E and F



Device type 09 <sup>1/</sup>

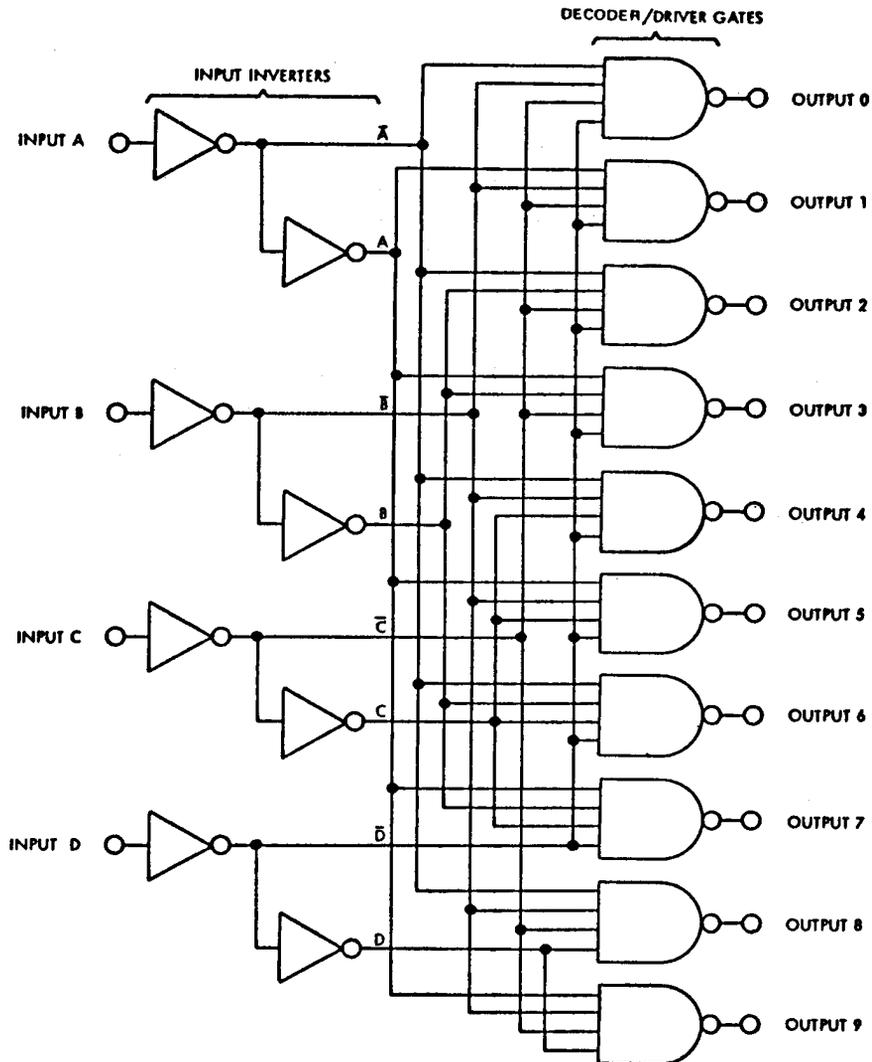
Cases A, B, C or D



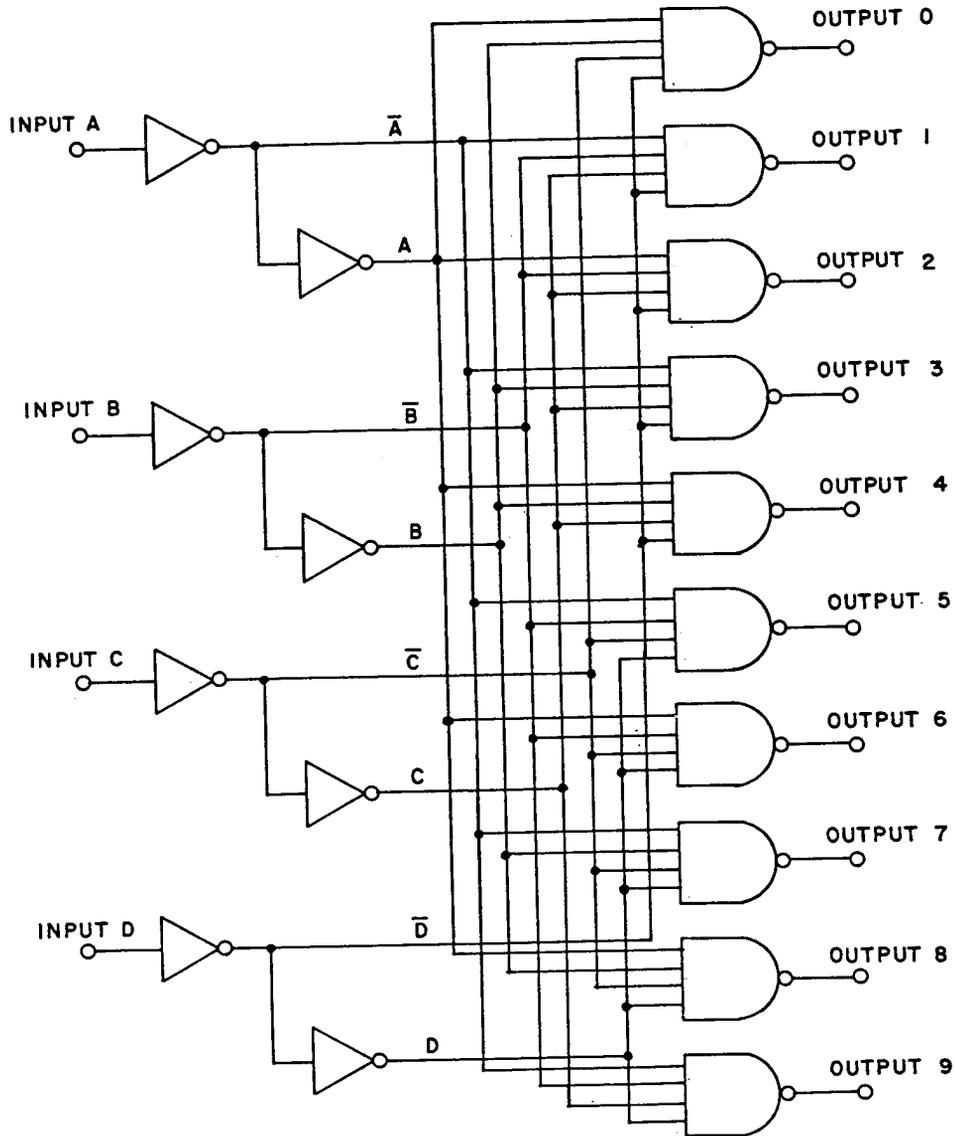
<sup>1/</sup> Qualification requirements are removed for device types 02, 03, 09.

FIGURE 1. Terminal connections.

Device types 01, 04, and 05

FIGURE 2. Logic diagrams.

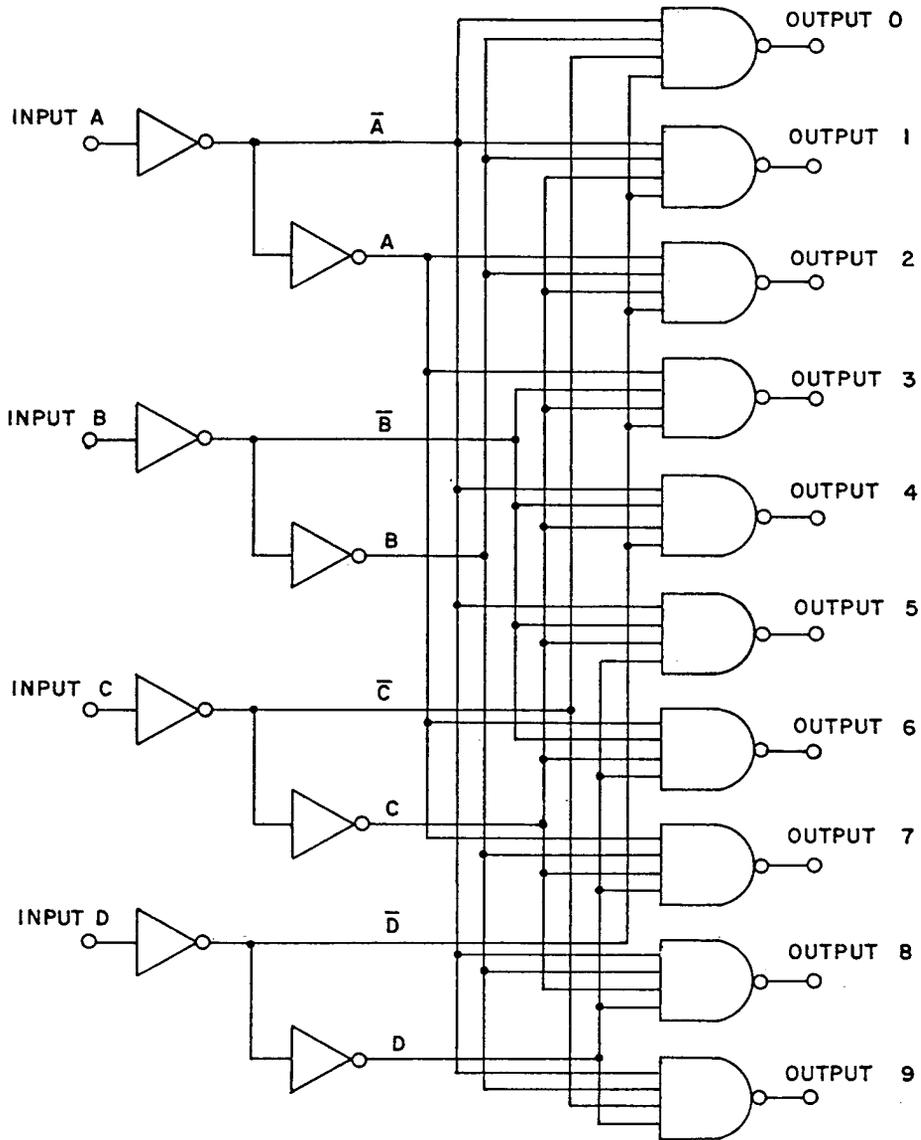
Device type 02 1/



1/ Qualification requirements are removed for this device type.

FIGURE 2. Logic diagrams. (Continued)

Device type 03 1/



1/ Qualification requirements are removed for this device type.

FIGURE 2. Logic diagrams. (Continued)

Device types 06 and 07

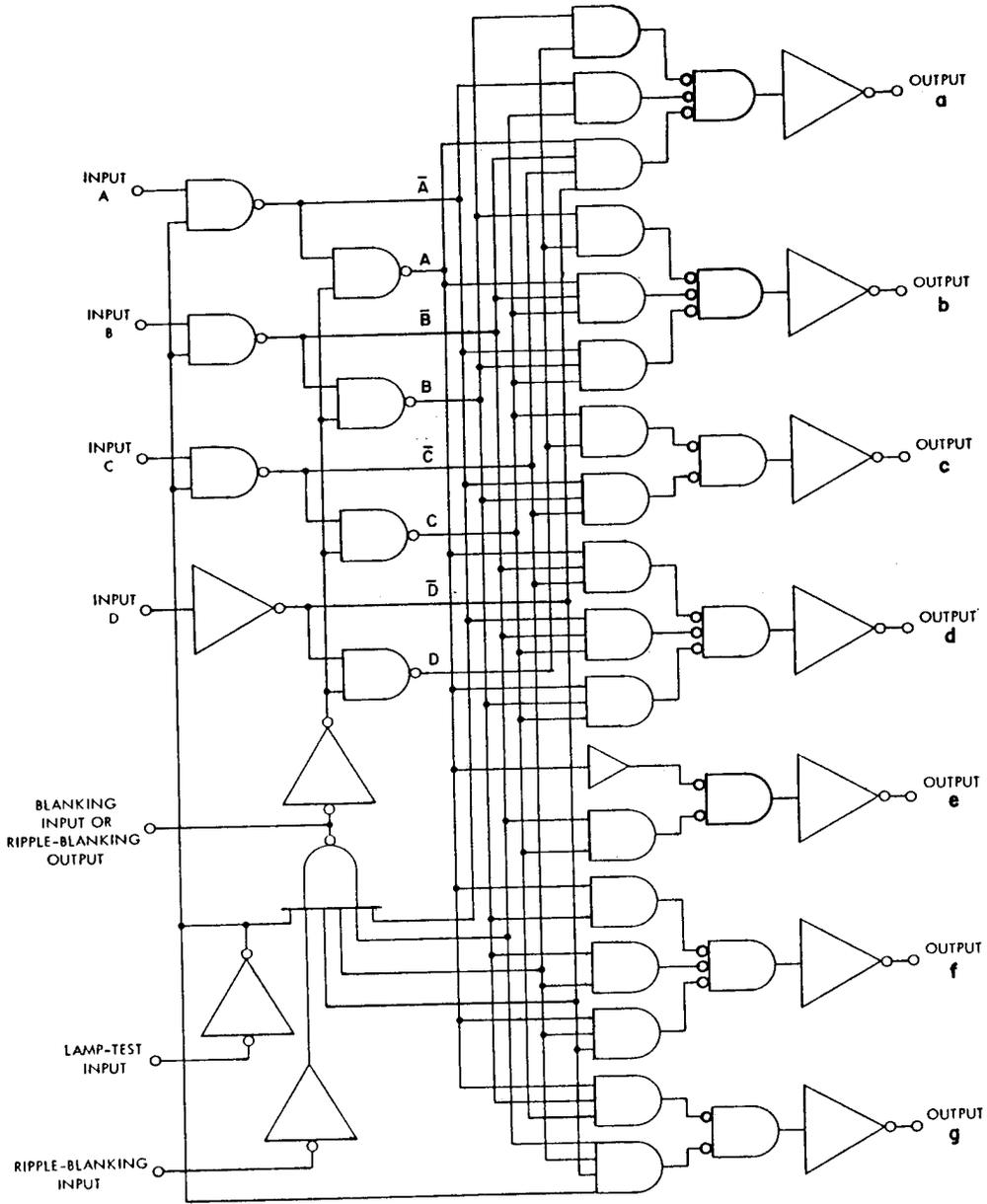
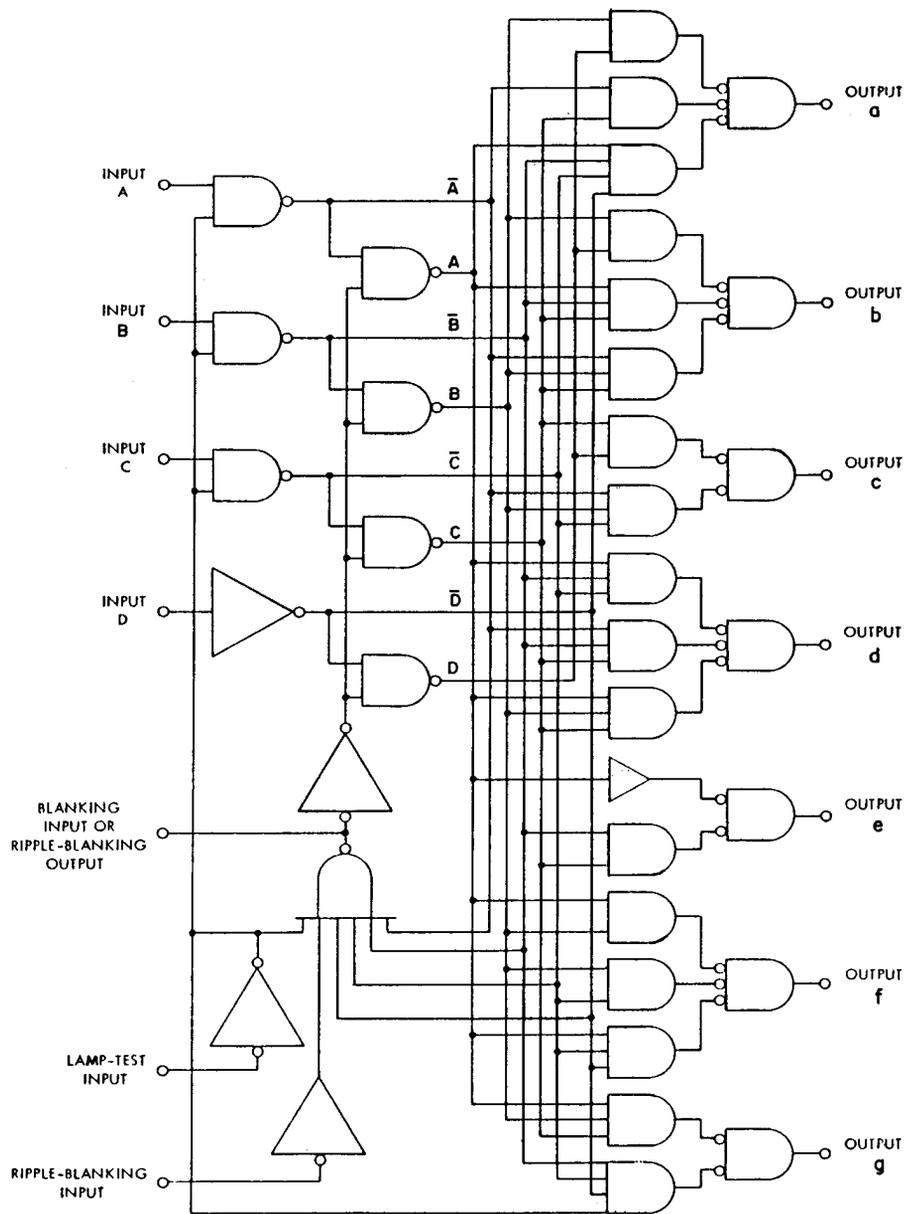
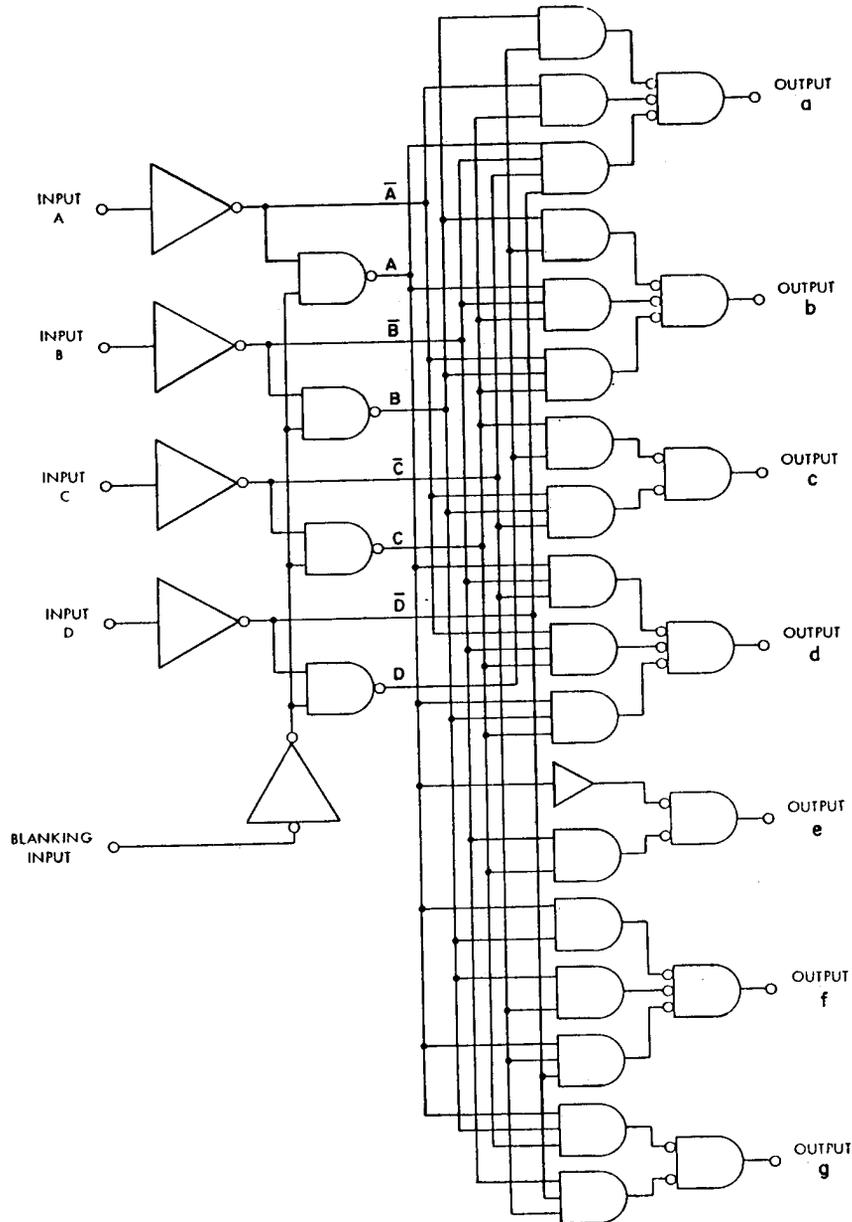


FIGURE 2. Logic diagrams. (Continued)

## Device type 08

FIGURE 2. Logic diagrams. (Continued)

Device type 09 1/



1/ Qualification requirements are removed for this device type.

FIGURE 2. Logic diagrams. (Continued)





Device type 06 and 07

DECIMAL OR FUNCTION	INPUTS							OUTPUTS							NOTE
	LT	RBI	D	C	B	A	BI/RBO	a	b	c	d	d	f	g	
0	H	H	L	L	L	L	H	L	L	L	L	L	L	H	1
1	H	X	L	L	L	H	H	H	L	L	H	H	H	H	1
2	H	X	L	L	H	H	H	L	L	H	L	L	H	L	
3	H	X	L	L	L	L	H	L	L	L	L	H	H	L	
4	H	X	L	H	L	L	H	H	L	L	H	H	L	L	
5	H	X	L	H	L	H	H	L	H	L	L	H	L	L	
6	H	X	L	H	H	L	H	H	H	L	L	L	L	L	
7	H	X	L	H	H	H	H	L	L	L	H	H	H	H	
8	H	X	H	L	L	L	H	H	L	L	L	L	L	L	
9	H	X	H	L	L	H	H	L	L	L	H	H	L	L	
10	H	X	H	L	H	L	H	H	H	H	L	L	H	L	
11	H	X	H	L	H	H	H	H	H	L	L	H	H	L	
12	H	X	H	H	L	L	H	H	L	L	H	H	L	L	
13	H	X	H	H	L	H	H	L	H	H	L	H	L	L	
14	H	X	H	H	H	L	H	H	H	H	L	L	L	L	
15	H	X	H	H	H	H	H	H	H	H	H	H	H	H	
BI	X	X	X	X	X	X	L	H	H	H	H	H	H	H	2
RBI	H	L	L	L	L	L	L	H	H	H	H	H	H	H	3
LT	L	X	X	X	X	X	H	L	L	L	L	L	L	L	4

## NOTES:

1. BI/RBO is wire-OR logic serving as blanking input (BI) and/or ripple-blanking output (RBO). The blanking input must be open or held at a high logic level when output functions 0 through 15 are desired, and ripple-blanking input (RBI) must be open or at a high logic level during the decimal 0 output. X = input may be high or low.
2. When a low logic level is applied to the blanking input (forced condition) all segment outputs go to a low logic level regardless of the state of any other input condition.
3. When ripple-blanking input (RBI) is at a low logic level, lamp test input is at high logic level and A = B = C = D = low logic level, all segment outputs go to a low logic level and the ripple-blanking output goes to a low logic level (response condition).
4. When blanking input/ripple-blanking output is open or held at a high logic level, and a low logic level is applied to lamp-test input, all segment outputs go to a high logic level.

FIGURE 3. Truth tables (Continued)

Device type 08

DECIMAL OR FUNCTION	INPUTS							OUTPUTS							NOTE
	LT	RBI	D	C	B	A	BI/RBO	a	b	c	d	d	f	g	
0	H	H	L	L	L	L	H	H	H	H	H	H	H	L	1 1
1	H	X	L	L	L	L	H	H	H	H	H	H	L	L	
2	H	X	L	L	L	H	H	H	H	L	H	L	L	H	
3	H	X	L	L	L	H	H	H	L	H	L	L	H	H	
4	H	X	L	L	H	L	H	H	L	L	H	L	H	H	
5	H	X	L	L	H	L	H	H	L	L	H	L	H	H	
6	H	X	L	L	H	H	H	H	L	L	H	L	L	H	
7	H	X	L	L	H	L	H	H	L	L	H	L	L	H	
8	H	X	L	L	L	L	H	H	L	L	L	L	L	H	
9	H	X	L	L	L	L	H	H	L	L	L	L	L	H	
10	H	X	L	L	L	L	H	H	L	L	L	L	L	H	
11	H	X	L	L	L	L	H	H	L	L	L	L	L	H	
12	H	X	L	L	L	L	H	H	L	L	L	L	L	H	
13	H	X	L	L	L	L	H	H	L	L	L	L	L	H	
14	H	X	L	L	L	L	H	H	L	L	L	L	L	H	
15	H	X	L	L	L	L	H	H	L	L	L	L	L	H	
BI	X	X	X	X	X	X	L	L	L	L	L	L	L	L	2 3 4
RBI	X	L	L	L	L	L	L	L	L	L	L	L	L	L	
LT	L	X	X	X	X	X	H	H	H	H	H	H	H	H	

## NOTES:

1. BI/RBO is wire-OR logic serving as blanking input (BI) and/or ripple-blanking output (RBO). The blanking input must be open or held at a high logic level when output functions 0 through 15 are desired, and ripple-blanking input (RBI) must be open or at a high logic level during the decimal 0 output. X = input may be high or low.
2. When a low logic level is applied to the blanking input (forced condition) all segment outputs go to a low logic level regardless of the state of any other input condition.
3. When ripple-blanking input (RBI) is at a low logic level, lamp test input is at high logic level and A = B = C = D = low logic level, all segment outputs go to a low logic level and the ripple-blanking output goes to a low logic level (response condition).
4. When blanking input/ripple-blanking output is open or held at a high logic level, and a low logic level is applied to lamp-test input, all segment outputs go to a high logic level.

FIGURE 3. Truth tables (Continued)

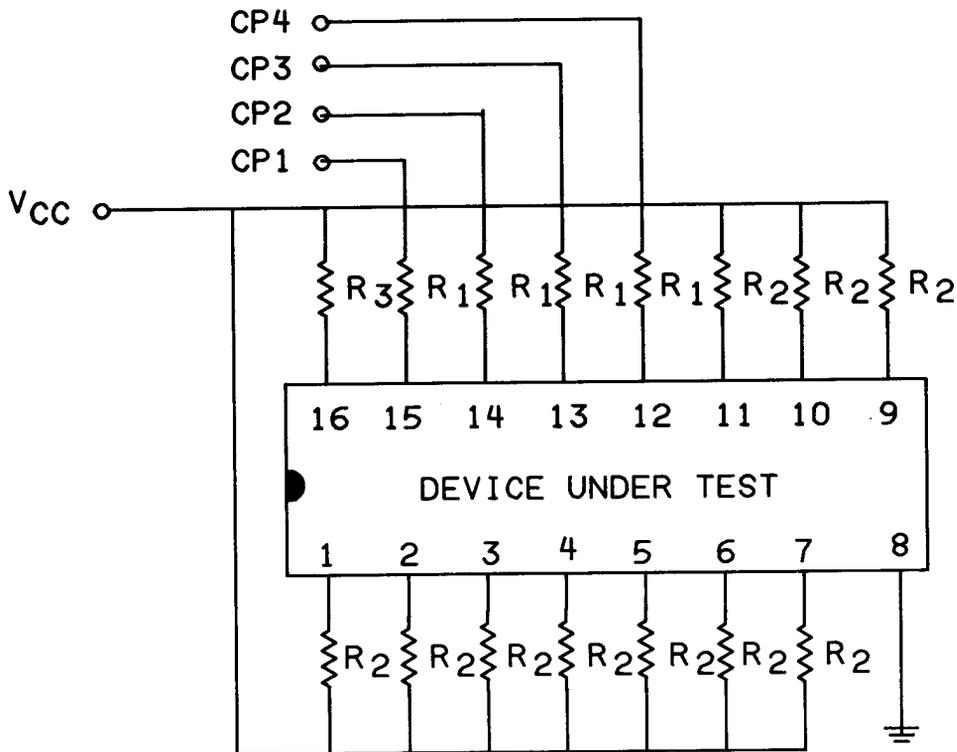
Device type 09

DECIMAL OR FUNCTION	INPUTS					OUTPUTS							NOTE
	D	C	B	A	BI	a	b	c	d	e	f	g	
0	L	L	L	L	H	H	H	H	H	H	H	L	1
1	L	L	L	H	H	H	H	H	L	H	L	L	
2	L	L	H	L	H	H	H	L	H	H	L	H	
3	L	L	H	H	H	H	H	H	H	L	L	H	
4	L	H	L	L	H	L	H	H	L	L	H	H	
5	L	H	L	H	H	H	L	H	H	L	H	H	
6	L	H	H	L	H	L	L	H	H	H	H	H	
7	L	H	H	H	H	H	H	H	L	L	L	L	
8	H	L	L	L	H	H	H	H	H	H	H	H	
9	H	L	L	H	H	H	H	H	L	L	H	H	
10	H	L	H	L	H	L	L	L	H	H	L	H	
11	H	L	H	H	H	L	L	L	H	L	L	H	
12	H	H	L	L	H	L	H	L	L	L	H	H	
13	H	H	L	H	H	H	L	L	H	L	H	H	
14	H	H	H	L	H	L	L	L	H	H	H	L	
15	H	H	H	H	H	L	L	L	L	L	L	L	
BI	X	X	X	X	L	L	L	L	L	L	L	L	2

- NOTES:
1. The blanking input must be open or held at a high logic level when output functions 0 through 15 are desired.
  2. When a low logic level is applied to the blanking input all segment outputs go to a low logic level regardless of the state of any other input condition. X = input may be high or low.
  3. Qualification requirements are removed for this device type.

FIGURE 3. Truth tables. (Continued)

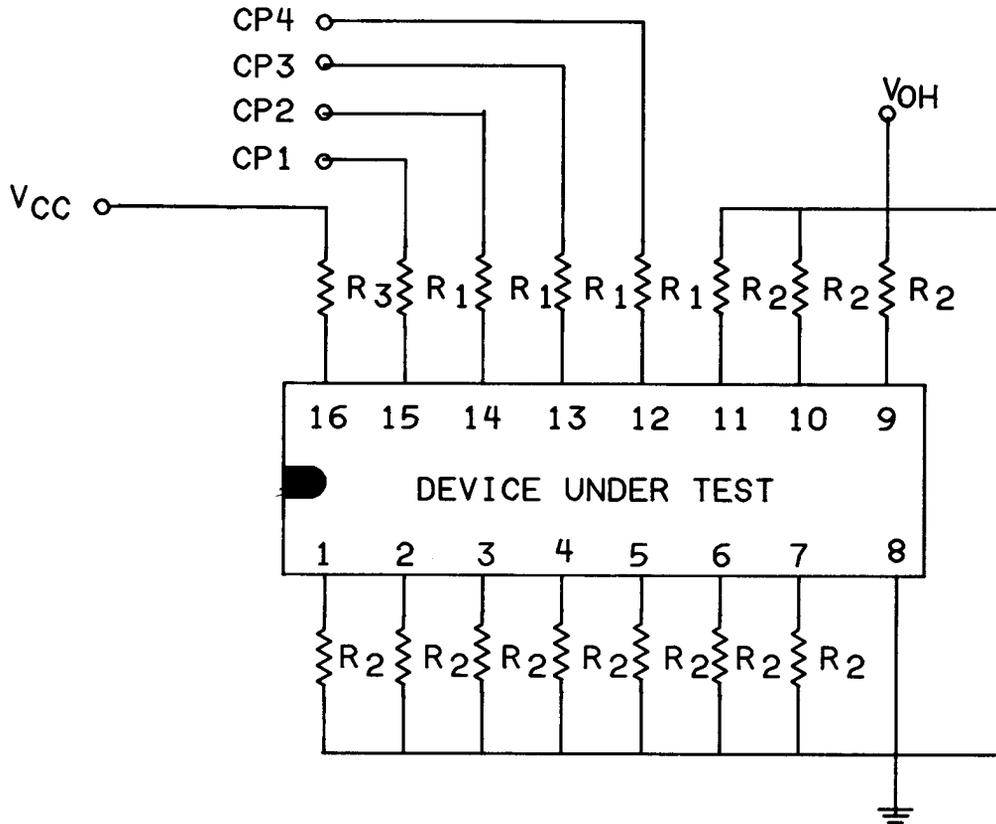
Device type 01, 02, and 03



## NOTES:

1.  $V_{CC}$  is such that the minimum voltage at the device terminals is 5 volts.
2.  $R_1 = 27\Omega \pm 5\%$ ;  $R_2 = 270\Omega \pm 5\%$ ;  $R_3 = 4.7\Omega \pm 5\%$ .
3. CP1 -- 100 kHz, with minimum  $V_{IN} = 3$  V, and minimum duty cycle of 50%.  
 CP2 -- 50 kHz, with minimum  $V_{IN} = 3$  V, and minimum duty cycle of 50%.  
 CP3 -- 25 kHz, with minimum  $V_{IN} = 3$  V, and minimum duty cycle of 50%.  
 CP4 -- 12.5 kHz, with minimum  $V_{IN} = 3$  V, and minimum duty cycle of 50%.
4. Qualification requirements are removed for device types 02, 03.

FIGURE 4. Burn-in and life test circuit.

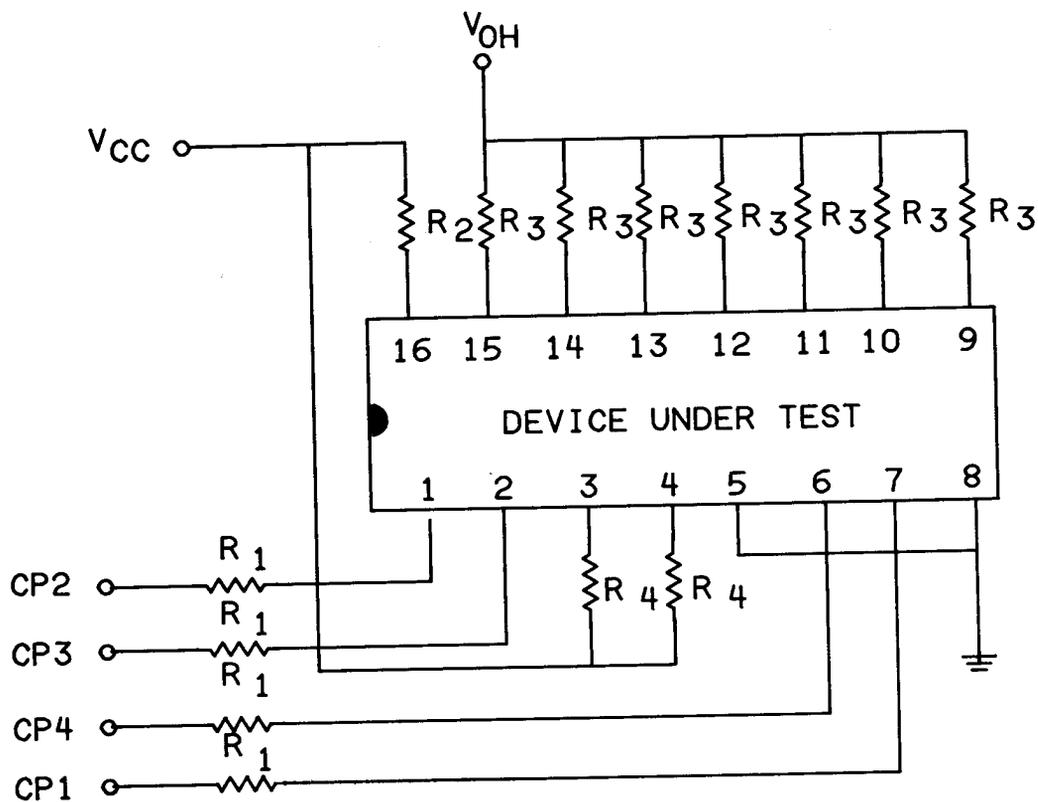
Device types 04 and 05

## NOTES:

- $V_{CC}$  is such that the minimum voltage at the device terminals is 5 volts.
- $R_1 = 27\Omega \pm 5\%$ ;  $R_3 = 4.7\Omega \pm 5\%$ .
- $R_2 = 400\Omega \pm 5\%$  for device type 04.  
 $R_2 = 200\Omega \pm 5\%$  for device type 05.
- $V_{OH}$  is such that the minimum voltage at the device terminals is 30 volts for device type 04 and 15 volts for device type 05.
- $CP_1$  -- 100 kHz, with minimum  $V_{IN} = 3$  V, and minimum duty cycle of 50%.
  - $CP_2$  -- 50 kHz, with minimum  $V_{IN} = 3$  V, and minimum duty cycle of 50%.
  - $CP_3$  -- 25 kHz, with minimum  $V_{IN} = 3$  V, and minimum duty cycle of 50%.
  - $CP_4$  -- 12.5 kHz, with minimum  $V_{IN} = 3$  V, and minimum duty cycle of 50%.

FIGURE 4. Burn-in and life test circuit - Continued.

## Device types 06 and 07

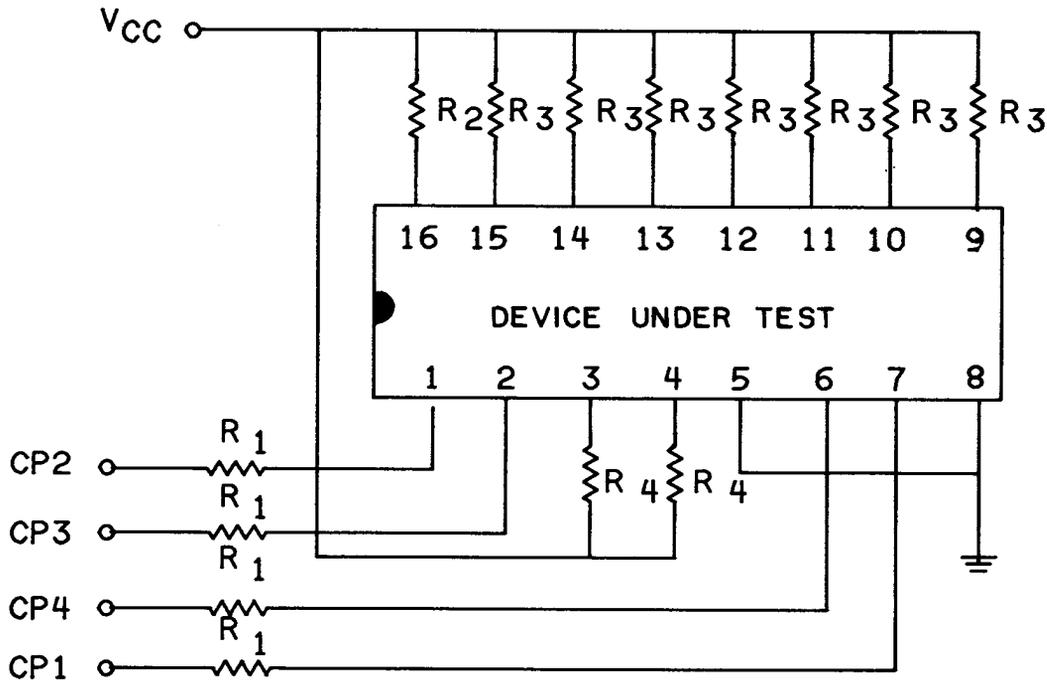


## NOTES:

1. V<sub>CC</sub> is such that the minimum voltage at the device terminals is 5 volts.
2. R<sub>1</sub> = 27Ω ±5%; R<sub>2</sub> = 4.7Ω ±5%; R<sub>4</sub> = 560Ω ±5%.
3. R<sub>3</sub> = 830Ω ±5% for device type 06.  
R<sub>3</sub> = 470Ω ±5% for device type 07.
4. V<sub>OH</sub> is such that the minimum voltage at the device terminals is 30 volts for device type 06 and 15 volts for device type 07.
5. CP1 -- 100 kHz, with minimum V<sub>IN</sub> = 3 V, and minimum duty cycle of 50%.  
CP2 -- 50 kHz, with minimum V<sub>IN</sub> = 3 V, and minimum duty cycle of 50%.  
CP3 -- 25 kHz, with minimum V<sub>IN</sub> = 3 V, and minimum duty cycle of 50%.  
CP4 -- 12.5 kHz, with minimum V<sub>IN</sub> = 3 V, and minimum duty cycle of 50%.

FIGURE 4. Burn-in and life test circuit - Continued.

Device type 08

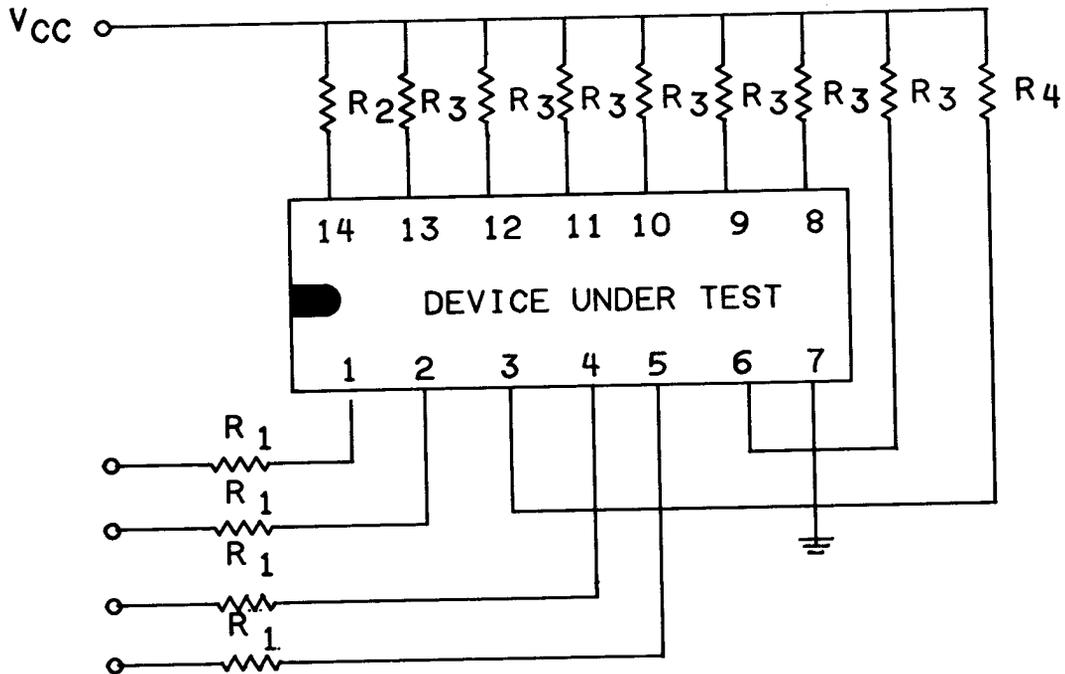


## NOTES:

1.  $V_{CC}$  is such that the minimum voltage at the device terminals is 5 volts.
2.  $R_1 = 27\Omega \pm 5\%$ ;  $R_2 = 4.7\Omega \pm 5\%$ ;  $R_3 = 820\Omega \pm 5\%$ ;  $R_4 = 560\Omega \pm 5\%$ .
3. CP1 -- 100 kHz, with minimum  $V_{IN} = 3$  V, and minimum duty cycle of 50%.  
 CP2 -- 50 kHz, with minimum  $V_{IN} = 3$  V, and minimum duty cycle of 50%.  
 CP3 -- 25 kHz, with minimum  $V_{IN} = 3$  V, and minimum duty cycle of 50%.  
 CP4 -- 12.5 kHz, with minimum  $V_{IN} = 3$  V, and minimum duty cycle of 50%.

FIGURE 4. Burn-in and life test circuit - Continued.

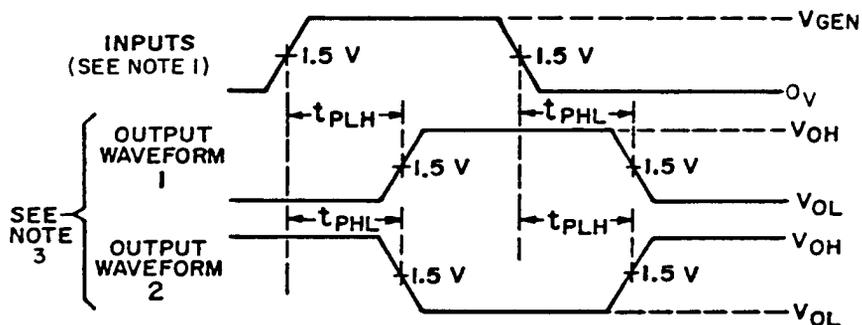
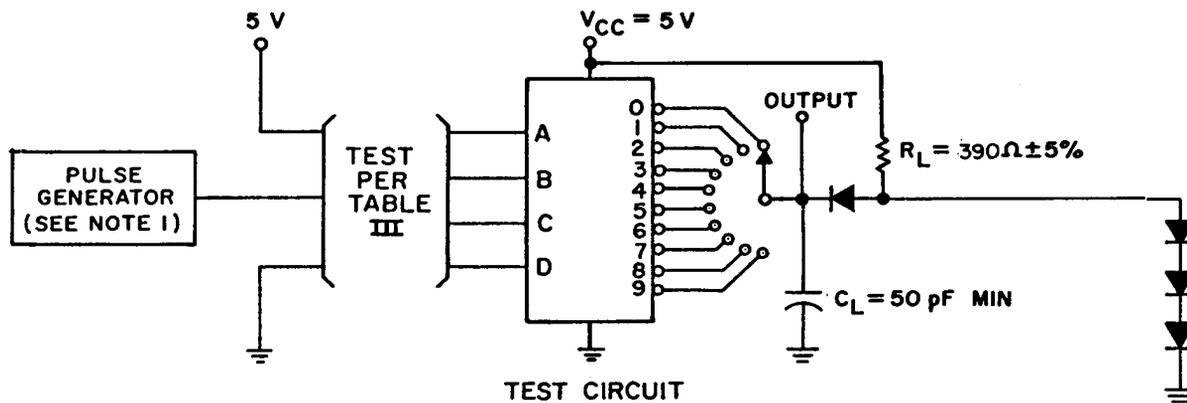
## Device type 09



## NOTES:

1.  $V_{CC}$  is such that the minimum voltage at the device terminals is 5 volts.
2.  $R_1 = 27\Omega \pm 5\%$ ;  $R_2 = 4.7\Omega \pm 5\%$ ;  $R_3 = 470\Omega \pm 5\%$ ;  $R_4 = 1\text{ k}\Omega \pm 5\%$ .
3. CP1 -- 100 kHz, with minimum  $V_{IN} = 3\text{ V}$ , and minimum duty cycle of 50%.  
 CP2 -- 50 kHz, with minimum  $V_{IN} = 3\text{ V}$ , and minimum duty cycle of 50%.  
 CP3 -- 25 kHz, with minimum  $V_{IN} = 3\text{ V}$ , and minimum duty cycle of 50%.  
 CP4 -- 12.5 kHz, with minimum  $V_{IN} = 3\text{ V}$ , and minimum duty cycle of 50%.
4. Qualification requirements are removed for this device type.

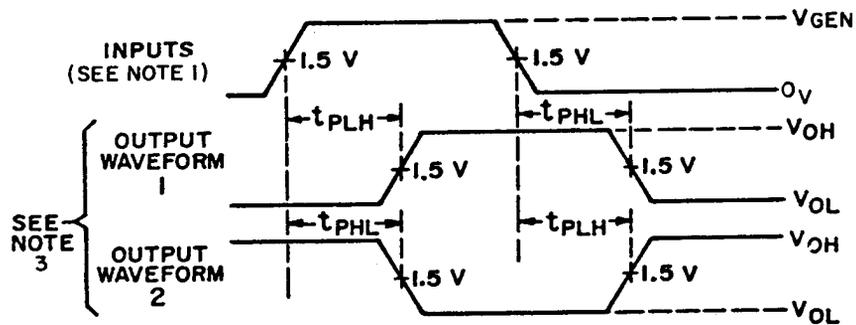
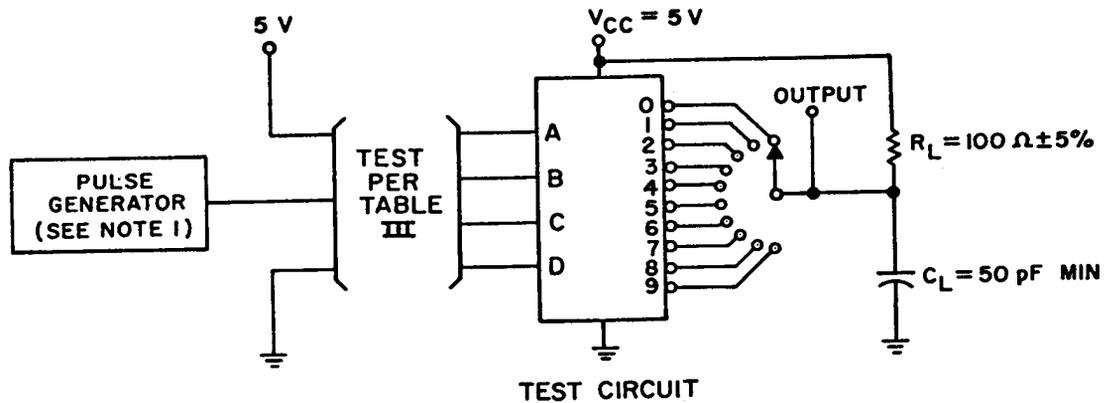
FIGURE 4. Burn-in and life test circuit - Continued.



## NOTES:

1. The pulse generator has the following characteristics:  $V_{gen} = 3.0$  V minimum,  $t_{PLH}$  (0.7 V to 2.7 V) and  $t_{PHL}$  (2.7 V to 0.7 V)  $\leq 10$  ns, PRR = 1 MHz, and minimum duty cycle = 50%.
2.  $C_L$  includes probe and jig capacitance.
3. Input - output waveform combination in accordance with the truth tables (see figure 3).
4. All diodes are 1N3064 or equivalent.
5. Qualification requirements are removed for device types 02, 03.

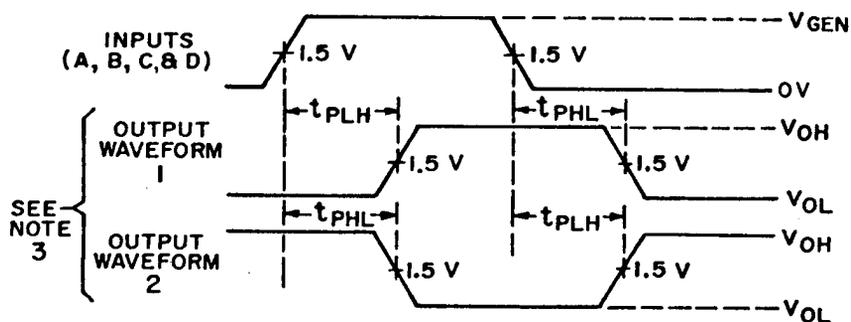
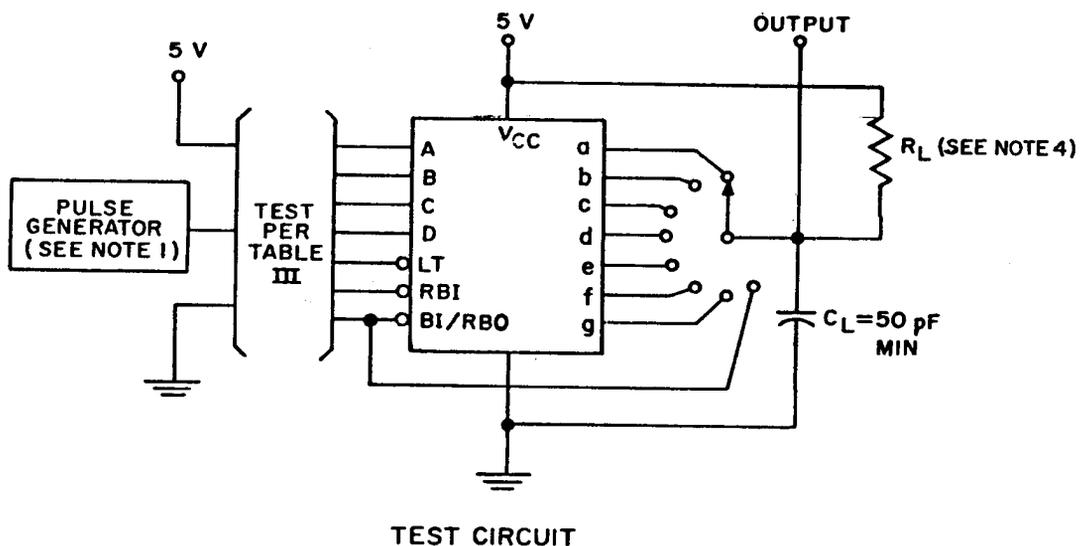
FIGURE 5. Switching times for device types 01, 02, and 03.



## NOTES:

1. The pulse generator has the following characteristics:  $V_{gen} = 3.0$  V minimum,  $t_{PLH}$  (0.7 V to 2.7 V) and  $t_{PHL}$  (2.7 V to 0.7 V)  $\leq 10$  ns, PRR = 1 MHz, and minimum duty cycle = 50%.
2.  $C_L$  includes probe and jig capacitance.
3. Input - output waveform combination in accordance with the truth tables (see figure 3).

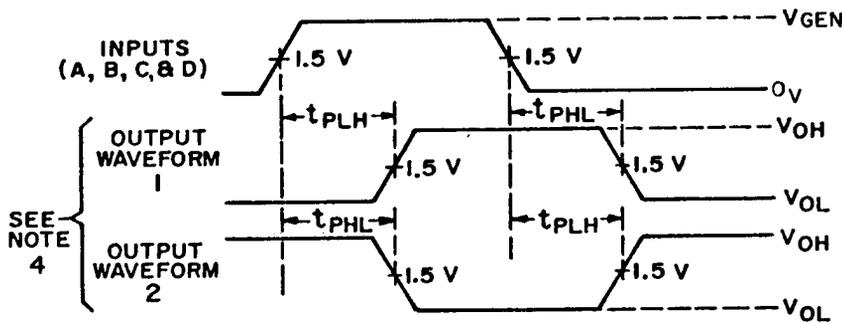
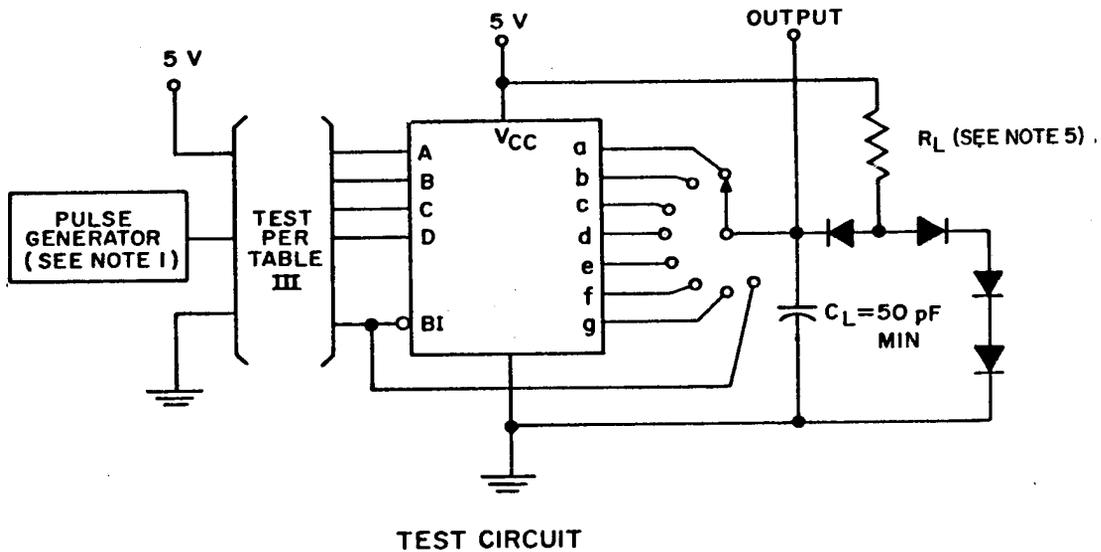
FIGURE 6. Switching times for device types 04 and 05.



## NOTES:

1. The pulse generator has the following characteristics:  $V_{gen} = 3.0 \text{ V}$  minimum,  $t_{TLH}$  (0.7 V to 2.7 V) and  $t_{THL}$  (2.7 V to 0.7 V)  $\leq 10 \text{ ns}$ , PRR = 1 MHz, and minimum duty cycle = 50%.
2.  $C_L$  includes probe and jig capacitance.
3. Input - output waveform combination in accordance with the truth tables (see figure 3).
4.  $R_L = 120\Omega \pm 5\%$  for outputs a thru g;  $R_L = 560\Omega \pm 5\%$  for output BI/RBO.

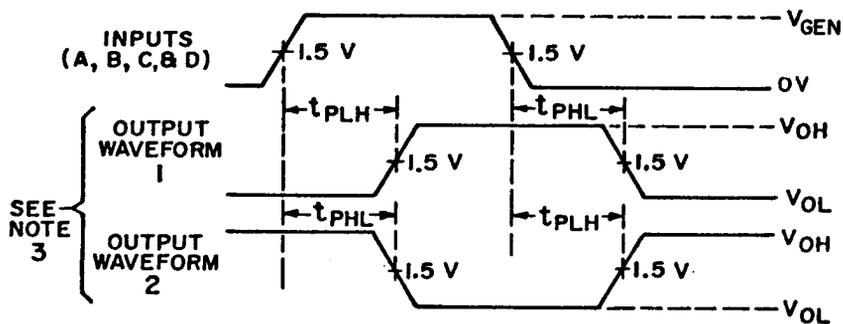
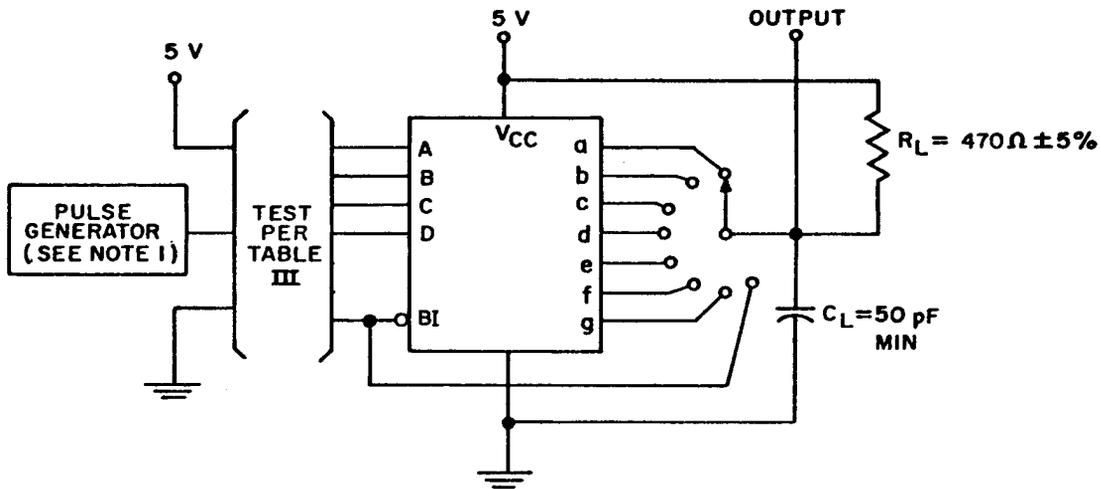
FIGURE 7. Switching times for device types 06 and 07.



## NOTES:

1. The pulse generator has the following characteristics:  $V_{gen} = 3.0 \text{ V}$  minimum,  $t_{TLH}$  (0.7 V to 2.7 V) and  $t_{THL}$  (2.7 V to 0.7 V)  $\leq 10 \text{ ns}$ ,  $PRR = 1 \text{ MHz}$ , and minimum duty cycle = 50%.
2.  $C_L$  includes probe and jig capacitance.
3. All diodes are 1N3064 or equivalent.
4. Input - output waveform combination in accordance with the truth tables (see figure 3).
5.  $R_L = 750\Omega \pm 5\%$  for outputs a thru g;  $R_L = 560\Omega \pm 5\%$  for output BI/RB0.

FIGURE 8. Switching times for device type 08.



## NOTES:

1. The pulse generator has the following characteristics:  $V_{gen} = 3.0$  V minimum,  $t_{TLH}$  (0.7 V to 2.7 V) and  $t_{THL}$  (2.7 V to 0.7 V)  $\leq 10$  ns, PRR = 1 MHz, and minimum duty cycle = 50%.
2.  $C_L$  includes probe and jig capacitance.
3. Input - output waveform combination in accordance with the truth tables (see figure 3).
4. Qualification requirements are removed for this device type.

FIGURE 9. Switching times for device type 09.









TABLE III. Group A inspection for device type 02 - Continued. 1/  
Terminal conditions (pins not designated may be high  $\geq 2.4$  V or low  $\leq 0.8$  V or open).

Subgroup	Symbol	MIL-STD-883 method	Cases E test no.	Terminal conditions											Test limits													
				1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	Measured terminal	Min	Max	Unit					
10	t <sub>pHL</sub> t <sub>pLH</sub>	3003 (Fig. 6)	144 & 145	0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	A to 1	5	39	ns				
			146 & 147																									
			148 & 149																									
			150 & 151	OUT																								
			152 & 153																									
			154 & 155																									
			156 & 157																									
			158 & 159																									
			160 & 161																									
			162 & 163																									
			164 & 165																									
			166 & 167	OUT																								
			170 & 171																									
			172 & 173																									
			174 & 175																									
			176 & 177																									
			178 & 179																									
			180 & 181																									
			182 & 183																									
184 & 185																												
186 & 187																												
188 & 189																												
190 & 191																												
11	Same tests, terminal conditions and limits as for subgroup 10 except T <sub>c</sub> = -55°C.																											

1/ Qualification requirements are removed for this device type.

2/ Output voltages shall be either:  
(a) H = 2.4 volts minimum and L = 0.4 volts maximum when using a high speed checker double comparator.  
or  
(b) H  $\geq$  1.5 volts and L  $\leq$  1.5 volts when using a high speed checker single comparator.

TABLE III. Group A Inspection for device type 03.  $\frac{1}{V}$   
Terminal conditions (pins not designated may be High  $\geq 2.4V$  or Low  $\leq 0.8V$  or open).

Subgroup	Symbol	MIL-STD-883 method	Cases E and F Test no.	Terminal conditions							Test limits												
				1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	Measured terminal	Min	Max	Unit
1	$V_{OH}$	3006	1	-0.8 mA																0	2.4	V	
			2	-0.8 mA																	1	"	"
			3	-0.8 mA																	2	"	"
			4	-0.8 mA																	3	"	"
			5	-0.8 mA																	4	"	"
			6	-0.8 mA																	5	"	"
			7	-0.8 mA																	6	"	"
			8	-0.8 mA																	7	"	"
			9	-0.8 mA																	8	"	"
			10	-0.8 mA																	9	"	"
	$V_{OL}$	3007	11	16 mA																0	10.4	V	
			12	16 mA																1	"	"	
			13	16 mA																2	"	"	
			14	16 mA																3	"	"	
			15	16 mA																4	"	"	
			16	16 mA																5	"	"	
			17	16 mA																6	"	"	
			18	16 mA																7	"	"	
			19	16 mA																8	"	"	
			20	16 mA																9	"	"	
	$V_{IC}$		21																	A	-1.5	V	
			22																	B	"	"	
			23																		C	"	"
			24																		D	"	"
	$I_{IH1}$	3010	25																	A	40	$\mu A$	
			26																	B	"	"	
			27																		C	"	"
			28																		D	"	"
	$I_{IH2}$	3010	29																	A	100	$\mu A$	
			30																	B	"	"	
			31																		C	"	"
			32																		D	"	"
	$I_{IL}$	3009	33																	A	-1.6	mA	
			34																	B	"	"	
			35																		C	"	"
			36																		D	"	"
	$I_{OS}$	3011	37	GND																0	-20	mA	
			38	GND																1	"	"	
			39	GND																2	"	"	
			40	GND																3	"	"	
			41	GND																4	"	"	
			42	GND																5	"	"	
			43	GND																6	"	"	
44	GND																7	"	"				
45	GND																8	"	"				
46	GND																9	"	"				
	$I_{CC}$	3005	47																	V <sub>CC</sub>	41	mA	

2 Same tests, terminal conditions and limits as for subgroup 1, except  $T_C = 125^\circ C$  and  $V_{IC}$  tests are omitted.

3 Same tests, terminal conditions and limits as for subgroup 1, except  $T_C = -55^\circ C$  and  $V_{IC}$  tests are omitted.

See notes at end of device type 03.





TABLE III. Group A inspection for device types 04 and 05.  
Terminal conditions (pins not designated may be high  $\geq 2.4$  V or low  $\leq 0.8$  V or open).

Subgroup	Symbol	MIL-STD-883 method	Cases E.F. Test no.	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	Measured terminal		Test limits			
				0	1	2	3	4	5	6	7	8	9	D	C	B	A	Vcc	terminal	Min	Max	Unit			
1 Tc = 25°C	V <sub>OL</sub>	3007	1	80 mA		80 mA	80 mA	80 mA								10.8 V	10.8 V	10.8 V	10.8 V	14.5 V	0		10.9	V	
			2	80 mA		80 mA	80 mA	80 mA									10.8 V	10.8 V	10.8 V	10.8 V	"	1		"	"
			3	80 mA		80 mA	80 mA	80 mA									10.8 V	10.8 V	10.8 V	10.8 V	"	2		"	"
			4	80 mA		80 mA	80 mA	80 mA									10.8 V	10.8 V	10.8 V	10.8 V	"	3		"	"
			5	80 mA		80 mA	80 mA	80 mA									10.8 V	10.8 V	10.8 V	10.8 V	"	4		"	"
			6	80 mA		80 mA	80 mA	80 mA									10.8 V	10.8 V	10.8 V	10.8 V	"	5		"	"
			7	80 mA		80 mA	80 mA	80 mA									10.8 V	10.8 V	10.8 V	10.8 V	"	6		"	"
			8	80 mA		80 mA	80 mA	80 mA									10.8 V	10.8 V	10.8 V	10.8 V	"	7		"	"
			9	80 mA		80 mA	80 mA	80 mA									10.8 V	10.8 V	10.8 V	10.8 V	"	8		"	"
			10	80 mA		80 mA	80 mA	80 mA									10.8 V	10.8 V	10.8 V	10.8 V	"	9		"	"
	V <sub>OL2</sub>	3007	11	20 mA		20 mA	20 mA	20 mA								10.8 V	10.8 V	10.8 V	10.8 V	"	0		10.4	"	
			12	20 mA		20 mA	20 mA	20 mA									10.8 V	10.8 V	10.8 V	10.8 V	"	1		"	"
			13	20 mA		20 mA	20 mA	20 mA									10.8 V	10.8 V	10.8 V	10.8 V	"	2		"	"
			14	20 mA		20 mA	20 mA	20 mA									10.8 V	10.8 V	10.8 V	10.8 V	"	3		"	"
			15	20 mA		20 mA	20 mA	20 mA									10.8 V	10.8 V	10.8 V	10.8 V	"	4		"	"
			16	20 mA		20 mA	20 mA	20 mA									10.8 V	10.8 V	10.8 V	10.8 V	"	5		"	"
			17	20 mA		20 mA	20 mA	20 mA									10.8 V	10.8 V	10.8 V	10.8 V	"	6		"	"
			18	20 mA		20 mA	20 mA	20 mA									10.8 V	10.8 V	10.8 V	10.8 V	"	7		"	"
			19	20 mA		20 mA	20 mA	20 mA									10.8 V	10.8 V	10.8 V	10.8 V	"	8		"	"
			20	20 mA		20 mA	20 mA	20 mA									10.8 V	10.8 V	10.8 V	10.8 V	"	9		"	"
	I <sub>CEX</sub> (See note 1)		21	Y	Y	Y	Y	Y	Y	Y						2.0 V	2.0 V	2.0 V	2.0 V	"	0		1250	μA	
			22	Y	Y	Y	Y	Y	Y	Y	Y						2.0 V	2.0 V	2.0 V	2.0 V	"	1		"	"
			23	Y	Y	Y	Y	Y	Y	Y	Y						2.0 V	2.0 V	2.0 V	2.0 V	"	2		"	"
			24	Y	Y	Y	Y	Y	Y	Y	Y						2.0 V	2.0 V	2.0 V	2.0 V	"	3		"	"
			25	Y	Y	Y	Y	Y	Y	Y	Y						2.0 V	2.0 V	2.0 V	2.0 V	"	4		"	"
			26	Y	Y	Y	Y	Y	Y	Y	Y						2.0 V	2.0 V	2.0 V	2.0 V	"	5		"	"
			27	Y	Y	Y	Y	Y	Y	Y	Y						2.0 V	2.0 V	2.0 V	2.0 V	"	6		"	"
			28	Y	Y	Y	Y	Y	Y	Y	Y						2.0 V	2.0 V	2.0 V	2.0 V	"	7		"	"
			29	Y	Y	Y	Y	Y	Y	Y	Y						2.0 V	2.0 V	2.0 V	2.0 V	"	8		"	"
			30	Y	Y	Y	Y	Y	Y	Y	Y						2.0 V	2.0 V	2.0 V	2.0 V	"	9		"	"
	V <sub>IC</sub>		31													-12 mA	-12 mA	-12 mA	-12 mA	"	A		-1.5	V	
			32													-12 mA	-12 mA	-12 mA	-12 mA	"	B		"	"	
			33													-12 mA	-12 mA	-12 mA	-12 mA	"	C		"	"	
			34													-12 mA	-12 mA	-12 mA	-12 mA	"	D		"	"	
	I <sub>I1</sub>	3009	35												5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	"	A		-7	-1.6	mA
			36													5.5 V	5.5 V	5.5 V	5.5 V	"	B		"	"	
			37													5.5 V	5.5 V	5.5 V	5.5 V	"	C		"	"	
			38													5.5 V	5.5 V	5.5 V	5.5 V	"	D		"	"	
	I <sub>I1H1</sub>	3010	39												GND	GND	GND	GND	2.4 V	"	A		40	μA	
			40													GND	GND	GND	2.4 V	"	B		"	"	
			41													GND	GND	GND	2.4 V	"	C		"	"	
			42													GND	GND	GND	2.4 V	"	D		"	"	
	I <sub>I1H2</sub>	3010	43												GND	GND	GND	5.5 V	5.5 V	"	A		100	μA	
			44													GND	GND	GND	5.5 V	GND	"	B		"	"
			45													GND	GND	GND	5.5 V	GND	"	C		"	"
			46													GND	GND	GND	5.5 V	GND	"	D		"	"
	I <sub>CC</sub>	3005	47											GND	GND	GND	GND	GND	"	Vcc		62	mA		
2	Same tests, terminal conditions and limits as for subgroup 1, except Tc = 125°C and V <sub>IC</sub> tests are omitted.																								
3	Same tests, terminal conditions and limits as for subgroup 1, except Tc = -55°C and V <sub>IC</sub> tests are omitted.																								

See notes at end of device types 04 and 05.

TABLE III. Group A inspection for device types 04 and 05 - Continued.  
Terminal conditions (pins not designated may be high  $\geq 2.4$  V or low  $\leq 0.8$  V or open).

Subgroup	Symbol	MIL-STD-883 method	Cases E,F test no.	Test Limits																							
				1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16								
				0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16							
																					Measured terminal	Unit					
																						Min	Max				
7 T <sub>C</sub> = 25°C	Truth table test		48	L	H	H	H	H	H	H	H	GND	H	H	H	H	H	GND	GND	GND	GND	GND					
				H	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L			
				"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"			
				"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"			
				"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"			
				"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"			
				"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"			
				"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"			
				"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"			
				"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"			
				"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"			
				"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"			
				8 T <sub>C</sub> = 25°C	Truth table test		64 thru 79	Same tests as subgroup 7, except T <sub>C</sub> = 125°C.																			
Same tests as subgroup 7, except T <sub>C</sub> = -55°C.																											
Same tests as subgroup 7, except T <sub>C</sub> = -55°C.																											
Same tests as subgroup 7, except T <sub>C</sub> = -55°C.																											
Same tests as subgroup 7, except T <sub>C</sub> = -55°C.																											
Same tests as subgroup 7, except T <sub>C</sub> = -55°C.																											
Same tests as subgroup 7, except T <sub>C</sub> = -55°C.																											
Same tests as subgroup 7, except T <sub>C</sub> = -55°C.																											
Same tests as subgroup 7, except T <sub>C</sub> = -55°C.																											
Same tests as subgroup 7, except T <sub>C</sub> = -55°C.																											
Same tests as subgroup 7, except T <sub>C</sub> = -55°C.																											
Same tests as subgroup 7, except T <sub>C</sub> = -55°C.																											
Same tests as subgroup 7, except T <sub>C</sub> = -55°C.																											
9 T <sub>C</sub> = 25°C	t <sub>pHL</sub> t <sub>pLH</sub>	3003 (Fig. 7)	96 & 97	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT			
				OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	
				OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
				OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
				OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
				OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
				OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
				OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
				OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
				OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
				OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
				OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT
				OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT	OUT

See notes at end of device types 04 and 05.



TABLE III. Group A inspection for device types 06 and 07.  
Terminal conditions (pins not designated may be high  $\geq 2.4$  V or low  $\leq 0.8$  V or open).

Subgroup	Symbol	MIL-STD-883 method	Cases E,F test no.	Terminal conditions																Test Limits						
				1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	Measured terminal	Unit					
1 $T_c = 25^\circ\text{C}$	VOL1 (See note 1)	3007	1	X	X	0.8 V					X	X	X	X	X	X	X	X	X	X	4.5 V	0.4 V				
			2	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"			
			3	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"		
			4	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"		
			5	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	
			6	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	
			7	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	
	VOL2	3007	8	0.8 V	0.8 V	2.0 V	8 mA	0.8 V	0.8 V	0.8 V	0.4 V															
			9	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"		
			10	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	
			11	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	
			12	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"
			13	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"
			14	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"
			15	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"
VOH	3006	16	0.8 V	0.8 V	2.0 V	2.0 V	0.8 V	0.8 V	0.4 V																	
		17	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"		
VIC		18	-12 mA	-12 mA																						
		19	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"		
		20	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	
		21	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"
		22	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"
		23	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"
IIL1	3009	23(See note 4)	10.4 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V				
		23 Ckt C	10.4 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V			
		24(See note 4)	15.5 V	0.4 V	0.4 V	0.4 V	0.4 V	0.4 V	0.4 V	0.4 V	0.4 V	0.4 V	0.4 V	0.4 V	0.4 V	0.4 V	0.4 V	0.4 V	0.4 V	0.4 V	0.4 V	0.4 V	0.4 V			
		24 Ckt C	15.5 V	0.4 V	0.4 V	0.4 V	0.4 V	0.4 V	0.4 V	0.4 V	0.4 V	0.4 V	0.4 V	0.4 V	0.4 V	0.4 V	0.4 V	0.4 V	0.4 V	0.4 V	0.4 V	0.4 V	0.4 V			
		25(See note 4)	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V			
		25 Ckt C	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V		
		26(See note 4)	10.4 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V		
		26 Ckt C	10.4 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V		
IIL2	3009	29	"	"	10.4 V	5.5 V	5.5 V	5.5 V																		
		30	2.4 V	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND			
		31	GND	2.4 V	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND		
		32	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"		
IIL3	3010	33	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"			
		34	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"		
		35	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	
		36	5.5 V	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	
		37	GND	5.5 V	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	
IIL4	3010	38	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"			
		39	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"		
		40	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	
		41	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	
IOS	3011	42	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"			
		43	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V		
ICC	3005	43	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V			
		44	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	
2				Same tests, terminal conditions and limits as for subgroup 1, except $T_c = 125^\circ\text{C}$ and $V_{IC}$ tests are omitted.																RBO	-1.7	-4.2				
				45	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"				"	"	"	"
3				Same tests, terminal conditions and limits as for subgroup 1, except $T_c = -55^\circ\text{C}$ and $V_{IC}$ tests are omitted.																RBO	-1.5	-1.3				
				46	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"				"	"	"	"

See notes at the end of device types 06 and 07.



TABLE III. Group A inspection for device types 06 and 07 - Continued  
Terminal conditions (pins not designated may be high  $\geq 2.4$  V or low  $\leq 0.8$  V or open).

Subgroup	Symbol	MIL-STD-883 method	Cases E,F test no.	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	Test Limits		Unit					
																				Measured	Terminal		Min	Max			
10	tPHL Tc = 125°C tPLH	3003 (Fig. 8)	189 & 190	GND	GND	5.0 V	LT	R80	RBI	D	IN	GND				OUT			5.0 V	A to a	8	144	ns				
			191 & 192	GND	5.0 V	"	"	"	"	"	"	"	"	"	"	"	"	OUT		"	"	"	"	"			
			193 & 194	5.0 V	"	"	"	"	"	"	"	"	"	"	"	"	"	OUT		"	"	"	"	"	"		
			195 & 196	GND	"	"	"	"	"	"	"	"	"	"	"	"	"	OUT		"	"	"	"	"	"	"	
			197 & 198	5.0 V	"	"	"	"	"	"	"	"	"	"	"	"	"	OUT		"	"	"	"	"	"	"	
			199 & 200	5.0 V	GND	"	"	"	"	"	"	"	"	"	"	"	"	OUT		"	"	"	"	"	"	"	
			201 & 202	GND	GND	"	"	"	"	"	"	"	"	"	"	"	"	OUT		"	"	"	"	"	"	"	"
			203 & 204	GND	5.0 V	"	"	"	"	"	"	"	"	"	"	"	"	OUT		"	"	"	"	"	"	"	"
			205 & 206	5.0 V	5.0 V	"	"	"	"	"	"	"	"	"	"	"	"	OUT		"	"	"	"	"	"	"	"
			207 & 208	GND	GND	"	"	"	"	"	"	"	"	"	"	"	"	OUT		"	"	"	"	"	"	"	"
			209 & 210	5.0 V	GND	"	"	"	"	"	"	"	"	"	"	"	"	OUT		"	"	"	"	"	"	"	"
			211 & 212	GND	GND	"	"	"	"	"	"	"	"	"	"	"	"	OUT		"	"	"	"	"	"	"	"
			213 & 214	5.0 V	5.0 V	"	"	"	"	"	"	"	"	"	"	"	"	OUT		"	"	"	"	"	"	"	"
			215 & 216	5.0 V	5.0 V	"	"	"	"	"	"	"	"	"	"	"	"	OUT		"	"	"	"	"	"	"	"
			217 & 218	GND	GND	"	"	"	"	"	"	"	"	"	"	"	"	OUT		"	"	"	"	"	"	"	"
			219 & 220	IN	IN	"	"	"	"	"	"	"	"	"	"	"	"	OUT		"	"	"	"	"	"	"	"
			221 & 222	GND	GND	"	"	"	"	"	"	"	"	"	"	"	"	OUT		"	"	"	"	"	"	"	"
			223 & 224	"	"	"	"	"	"	"	"	"	"	"	"	"	"	OUT		"	"	"	"	"	"	"	"
			225 & 226	"	"	"	"	"	"	"	"	"	"	"	"	"	"	OUT		"	"	"	"	"	"	"	"
			227 & 228	"	"	"	"	"	"	"	"	"	"	"	"	"	"	OUT		"	"	"	"	"	"	"	"
			229 & 230	"	"	"	"	"	"	"	"	"	"	"	"	"	"	OUT		"	"	"	"	"	"	"	"
			231 & 232	"	"	"	"	"	"	"	"	"	"	"	"	"	"	OUT		"	"	"	"	"	"	"	"
			233 & 234	"	"	"	"	"	"	"	"	"	"	"	"	"	"	OUT		"	"	"	"	"	"	"	"
			235 & 236	"	"	"	"	"	"	"	"	"	"	"	"	"	"	OUT		"	"	"	"	"	"	"	"
			237 & 238	"	"	"	"	"	"	"	"	"	"	"	"	"	"	OUT		"	"	"	"	"	"	"	"
			239 & 240	"	"	"	"	"	"	"	"	"	"	"	"	"	"	OUT		"	"	"	"	"	"	"	"
			241 & 242	"	"	"	"	"	"	"	"	"	"	"	"	"	"	OUT		"	"	"	"	"	"	"	"
243 & 244	"	"	"	"	"	"	"	"	"	"	"	"	"	"	OUT		"	"	"	"	"	"	"	"			
245 & 246	"	"	"	"	"	"	"	"	"	"	"	"	"	"	OUT		"	"	"	"	"	"	"	"			
247 & 248	"	"	"	"	"	"	"	"	"	"	"	"	"	"	OUT		"	"	"	"	"	"	"	"			
249 & 250	"	"	"	"	"	"	"	"	"	"	"	"	"	"	OUT		"	"	"	"	"	"	"	"			
251 & 252	"	"	"	"	"	"	"	"	"	"	"	"	"	"	OUT		"	"	"	"	"	"	"	"			
253 & 254	"	"	"	"	"	"	"	"	"	"	"	"	"	"	OUT		"	"	"	"	"	"	"	"			
255 & 256	"	"	"	"	"	"	"	"	"	"	"	"	"	"	OUT		"	"	"	"	"	"	"	"			
257 & 258	"	"	"	"	"	"	"	"	"	"	"	"	"	"	OUT		"	"	"	"	"	"	"	"			
259 & 260	"	"	"	"	"	"	"	"	"	"	"	"	"	"	OUT		"	"	"	"	"	"	"	"			
261 & 262	"	"	"	"	"	"	"	"	"	"	"	"	"	"	OUT		"	"	"	"	"	"	"	"			
263 & 264	"	"	"	"	"	"	"	"	"	"	"	"	"	"	OUT		"	"	"	"	"	"	"	"			
265 & 266	"	"	"	"	"	"	"	"	"	"	"	"	"	"	OUT		"	"	"	"	"	"	"	"			
267 & 268	"	"	"	"	"	"	"	"	"	"	"	"	"	"	OUT		"	"	"	"	"	"	"	"			
269 & 270	"	"	"	"	"	"	"	"	"	"	"	"	"	"	OUT		"	"	"	"	"	"	"	"			
271 & 272	"	"	"	"	"	"	"	"	"	"	"	"	"	"	OUT		"	"	"	"	"	"	"	"			
273 & 274	"	"	"	"	"	"	"	"	"	"	"	"	"	"	OUT		"	"	"	"	"	"	"	"			
275 & 276	"	"	"	"	"	"	"	"	"	"	"	"	"	"	OUT		"	"	"	"	"	"	"	"			
11	Same tests terminal conditions and limits as for subgroup 10, except Tc = -55°C.																										

1/ X = Input may be high level or low level.  
 2/ Y = 30 volts for device type 05 and 15 volts for device type 07.  
 3/ Output voltages shall be either:  
 (a) H = 2.4 volts minimum and L = 0.4 volts minimum when using high speed checker double comparator, or  
 (b) H  $\geq$  1.5 volts and L  $\leq$  1.5 volts when using a high speed checker single comparator.  
 4/ CKT except C.



TABLE III. Group A Inspection for device type 08 - Continued.  
Terminal conditions (pins not designated may be high  $\geq 2.4V$  or low  $\leq 0.8V$  or open).

Subgroup	MIL-STD-883 test method	Cases E,F test no.	Terminal conditions																Test limits			
			1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	Measured terminal	Unit		
2	Same tests, terminal conditions and limits as for subgroup 1, except $T_C = 125^\circ C$ and VIC tests are omitted.																					
3	Same tests, terminal conditions and limits as for subgroup 1, except $T_C = -55^\circ C$ and VIC tests are omitted.																					
7 $T_C = 25^\circ C$	Truth table test	51	GND	GND	5.0 V	5.0 V	GND	GND	H	H	H	H	H	H	H	L	H	5.0 V				
			5.0 V	5.0 V	X	X	GND	GND	L	L	L	L	L	L	L	L	L	L				
			5.0 V	5.0 V	"	"	"	"	"	"	L	L	L	L	L	L	L	L				
			5.0 V	5.0 V	"	"	"	"	"	"	L	L	L	L	L	L	L	L				
			5.0 V	5.0 V	"	"	"	"	"	"	L	L	L	L	L	L	L	L				
			5.0 V	5.0 V	"	"	"	"	"	"	L	L	L	L	L	L	L	L				
			5.0 V	5.0 V	"	"	"	"	"	"	L	L	L	L	L	L	L	L				
			5.0 V	5.0 V	"	"	"	"	"	"	L	L	L	L	L	L	L	L				
			5.0 V	5.0 V	"	"	"	"	"	"	L	L	L	L	L	L	L	L				
			5.0 V	5.0 V	"	"	"	"	"	"	L	L	L	L	L	L	L	L				
			5.0 V	5.0 V	"	"	"	"	"	"	L	L	L	L	L	L	L	L				
			5.0 V	5.0 V	"	"	"	"	"	"	L	L	L	L	L	L	L	L				
			5.0 V	5.0 V	"	"	"	"	"	"	L	L	L	L	L	L	L	L				
			5.0 V	5.0 V	"	"	"	"	"	"	L	L	L	L	L	L	L	L				
8	Same tests as subgroup 7, except $T_C = 125^\circ C$ .																					
	Same tests as subgroup 7, except $T_C = -55^\circ C$ .																					
9 $T_C = 25^\circ C$	3003 (Fig. 9) tPHL tPLH	110 & 111 112 & 113 114 & 115 116 & 117 118 & 119 120 & 121 122 & 123 124 & 125 126 & 127 130 & 131 132 & 133 134 & 135 136 & 137 138 & 139 140 & 141 142 & 143 144 & 145 146 & 147 148 & 149 150 & 151 152 & 153 154 & 155	GND	GND	5.0 V	5.0 V	GND	GND	IN	IN	IN	IN	IN	IN	IN	IN	IN	5.0 V	A to a	ns		
			5.0 V	5.0 V	"	"	"	"	"	"	OUT	5.0 V	A to d	"								
			5.0 V	5.0 V	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	5.0 V	A to e	"
			5.0 V	5.0 V	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	5.0 V	A to f	"
			5.0 V	5.0 V	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	5.0 V	A to g	"
			5.0 V	5.0 V	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	5.0 V	A to h	"
			5.0 V	5.0 V	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	5.0 V	A to i	"
			5.0 V	5.0 V	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	5.0 V	A to j	"
			5.0 V	5.0 V	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	5.0 V	A to k	"
			5.0 V	5.0 V	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	5.0 V	A to l	"
			5.0 V	5.0 V	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	5.0 V	A to m	"
			5.0 V	5.0 V	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	5.0 V	A to n	"
			5.0 V	5.0 V	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	5.0 V	A to o	"
			5.0 V	5.0 V	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	5.0 V	A to p	"

See notes at end of device type 08.





TABLE III. Group A inspection for device type 09 - Continued. 1/  
Terminal conditions (pins not designated maybe high  $\geq 2.4$  V or low  $\leq 0.8$  V or open).

Subgroup	Symbol	MIL-STD-883 method	Cases A, B, D, C	Limits																		
				1	2	3	4	5	6	7	8	9	10	11	12	13	14	Measured Terminal	Min	Max	Unit	
8	Truth table test		153 to 69	1	2	3	4	5	6	7	8	9	10	11	12	13	14	VCC				
				I	C	3	4	5	6	7	8	9	10	11	12	13	14					
9	t <sub>pHL</sub> t <sub>pLH</sub>	3003 (Fig. 10)	77 & 78 79 & 80 81 & 82 83 & 84 85 & 86 87 & 88 89 & 90 91 & 92 93 & 94 95 & 96 97 & 98 99 & 100 101 & 102 103 & 104 105 & 106 107 & 108 109 & 110 111 & 112 113 & 114 115 & 116	GND	GND	5.0 V	GND	IN	OUT	GND	OUT	OUT	OUT	OUT	OUT	OUT	OUT	5.0 V	A to a A to d A to e A to f A to a A to b A to d B to c B to f B to g B to a B to e B to g C to d C to b D to g D to b BI to c BI to a	8	104	ns
				GND	GND	5.0 V	IN	OUT	GND	5.0 V	OUT	GND	5.0 V	OUT	OUT	OUT	OUT	OUT	OUT	5.0 V	A to a A to d A to e A to f A to a A to b A to d B to c B to f B to g B to a B to e B to g C to d C to b D to g D to b BI to c BI to a	8
10	t <sub>pHL</sub> t <sub>pLH</sub>		117 & 118 119 & 120 121 & 122 123 & 124 125 & 126 127 & 128 129 & 130 131 & 132 133 & 134 135 & 136 137 & 138 139 & 140 141 & 142 143 & 144 145 & 146 147 & 148 149 & 150 151 & 152 153 & 154 155 & 156	GND	GND	5.0 V	GND	IN	OUT	GND	OUT	OUT	OUT	OUT	OUT	OUT	OUT	5.0 V	A to a A to d A to e A to f A to a A to b A to d B to c B to f B to g B to a B to e B to g C to d C to b D to g D to b BI to c BI to a	8	104	ns
				GND	GND	5.0 V	IN	OUT	GND	5.0 V	OUT	GND	5.0 V	OUT	OUT	OUT	OUT	OUT	OUT	5.0 V	A to a A to d A to e A to f A to a A to b A to d B to c B to f B to g B to a B to e B to g C to d C to b D to g D to b BI to c BI to a	8
11	Same tests, terminal conditions and limits as for subgroup 10, except T <sub>c</sub> = -55°C.																					

1/ Qualification requirement are removed for this device type.  
2/ X = Input may be high or low.  
3/ Output voltages shall be either:  
(a) H = 2.4 volts minimum and L = 0.4 volts maximum when using a high speed checker double comparator, or  
(b) H  $\geq$  1.5 volts and L  $\leq$  1.5 volts when using a high speed checker single comparator.

**4.3 Qualification inspection.** Qualification inspection shall be in accordance with MIL-M-38510. Inspections to be performed shall be those specified in method 5005 of MIL-STD-883 and herein for groups A, B, C, and D inspections (see 4.4.1 through 4.4.4). Qualification inspection is not required for device types 02, 03, and 09.

**4.4 Quality conformance inspection.** Quality conformance inspection shall be in accordance with MIL-M-38510 and as specified herein. Inspections to be performed shall be those specified in method 5005 of MIL-STD-883 and herein for groups A, B, C, and D inspections (see 4.4.1 through 4.4.4). Generic test data (see 6.6) may be used to satisfy the requirements for groups C and D inspections. Quality conformance inspection shall be completed on the specific devices covered by this specification before they are shipped.

**4.4.1 Group A inspection.** Group A inspection shall be in accordance with table I of method 5005 of MIL-STD-883 and as follows:

- a. Electrical tests requirements shall be as specified in table II herein.
- b. Subgroups 4, 5, and 6, of table I of method 5005 of MIL-STD-883 shall be omitted.

**4.4.2 Group B inspection.** Group B inspection shall be in accordance with table II of method 5005 of MIL-STD-883. Electrical test requirements for device types 01, and 03 shall be as specified in table II herein.

**4.4.3 Group C inspection.** Group C inspection shall be in accordance with table III of method 5005 of MIL-STD-883 and as follows:

- a. End-point electrical parameters shall be as specified in table II herein.
- b. Steady-state life test (method 1005 of MIL-STD-883) conditions:
  - (1) Test condition D or E, using the circuit shown on figure 4, or equivalent.
  - (2)  $T_A = +125^\circ\text{C}$  minimum.
  - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

**4.4.4 Group D inspection.** Group D inspection shall be in accordance with table IV of method 5005 of MIL-STD-883. End-point electrical tests shall be as specified in table II herein.

**4.5 Methods of inspection.** Methods of inspection shall be specified as follows:

**4.5.1 Voltage and current.** All voltages given are referenced to the microcircuit ground terminal. Currents given are conventional and positive when flowing into the referenced terminal.

## 5. PACKAGING

**5.1 Packaging requirements.** The requirements for packaging shall be in accordance with MIL-M-38510.

## 6. NOTES

**6.1 Intended use.** Microcircuits conforming to this specification are intended for original equipment design applications and logistic support of existing equipment. Device types 02, 03, and 09 are intended for use for logistics support of existing equipment.

**6.2 Ordering data.** The acquisition document should specify the following:

- a. Complete part number (see 1.2).
- b. Requirements for delivery of one copy of the quality conformance inspection data pertinent to the device inspection lot to be supplied with each shipment by the device manufacturer, if applicable.

- c. Requirements for certificate of compliance, if applicable.
- d. Requirements for notification of change of product or process to the contracting activity for device types 02, 03, and 09. In addition to that, notification to the qualifying activity for device types 01, 04, 05, 06, 07, and 08, if applicable.
- e. For device types 01, 04, 05, 06, 07, and 08 requirements for failure analysis (including required test condition of method 5003 of MIL-STD-883), corrective action and reporting of results, if applicable.
- f. Requirements for product assurance options, device types 01, 04, 05, 06, 07, and 08. Requirements for packaging and packing, device types 02, 03, and 09.
- g. Requirements for special carriers, lead lengths, or lead forming, if applicable. These requirements shall not affect the part number. Unless otherwise specified, these requirements shall not apply to direct purchase by or direct shipment to the Government.
- h. Requirements for "JAN" marking. This shall apply to device types 01, 04, 05, 06, 07, and 08 only.

6.3 Abbreviations, symbols, and definitions. The abbreviations, symbols, and definitions used herein are defined in MIL-M-38510, MIL-STD-1331, and as follows:

GND	-----	Ground zero voltage potential.
I <sub>IN</sub>	-----	Current flowing into an input terminal.
V <sub>IN</sub>	-----	Voltage level at an input terminal.

6.4 Logistic support. Lead materials and finishes (see 3.3) are interchangeable. Unless otherwise specified, microcircuits acquired for Government logistic support will be acquired to device class B (see 1.2.2), lead material and finish C (see 3.3). Longer length leads and lead forming shall not affect the part number.

6.5 Generic test data. Generic test data may be used to satisfy the requirements of 4.4.3. Group C generic test data shall be on date codes no more than 1 year old and on a die in the same microcircuit group (see appendix E of MIL-M-38510) with the same material, design, and process and from the same plant as the die represented. Group D generic data shall be on date codes no more than 1 year old and on the same package type (see terms, definitions, and symbols of MIL-M-38510) and from the same plant as the package represented. The vendor is required to retain the generic data for a period of not less than 36 months from the date of shipment.

6.6 Substitutability. The cross-reference information below is presented for the convenience of users. Microcircuits covered by this specification will functionally replace the listed generic-industry type. Generic-industry microcircuit types may not have equivalent operational performance characteristics across military temperature ranges or reliability factors equivalent to MIL-M-38510 device types and may have slight physical variations in relation to case size. The presence of this information shall not be deemed as permitting substitution of generic-industry types for MIL-M-38510 types or as a waiver of any of the provisions of MIL-M-38510.

<u>Military device type</u>	<u>Generic-industry type</u>
01	5442
02 5/	5443
03 5/	5444
04	5445
05	54145
06	5446
07	5447
08	5448
09 5/	5449

5/ Qualification requests are removed for this device type.

6.7 Manufacturers' designators. Manufacturers' circuits included in this specification are designated as shown in table IV herein.

TABLE IV. Manufacturers' designations.

Device type	Circuit				
	Texas Instru- ment Incorporated	Signetics Corporation	National Semi- Conductor Corporation	Moto-ola Incorporated	Fairchild
01	D	C	E	B	A
04	C	A	E	B	D
05	C	A	E	B	D
06	C	B	D		
07	C	B	D		
08	B	C	E	A	

6.8 Ordering guidance. Since the qualification and certification requirements have been removed from the specification for device types 02, 03, and 09, orders may be specified immediately.

6.9 Changes from previous issue. Asterisks are not used in this revision to identify changes with respect to the previous issue, due to the extensiveness of the changes.

**Custodians:**

Army - ER  
Navy - EC  
Air Force - 17

**Review activities:**

Army - AR, MI  
Navy - OS, SH, TD  
Air Force - 11, 19, 85, 99  
DLA - ES

**User activities:**

Army - SM  
Navy - AS, CG, MC

**Preparing activity:**  
Air Force - 17

**Agent:**  
DLA - ES

(Project 5962-0902)